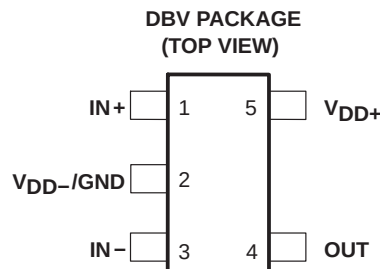


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- **Output Swing Includes Both Supply Rails**
- **Low Noise . . . 19 nV/√Hz Typ at f = 1 kHz**
- **Low Input Bias Current . . . 1 pA Typ**
- **Fully Specified for Single-Supply 3-V and 5-V Operation**
- **Very Low Power . . . 110 μA Typ**
- **Common-Mode Input Voltage Range Includes Negative Rail**
- **Wide Supply Voltage Range 2.7 V to 10 V**
- **Macromodel Included**



description

The TLV2221 is a single low-voltage operational amplifier available in the SOT-23 package. It offers a compromise between the ac performance and output drive of the TLV2231 and the micropower TLV2211.

It consumes only 150 μA (max) of supply current and is ideal for battery-powered applications. The device exhibits rail-to-rail output performance for increased dynamic range in single- or split-supply applications. The TLV2221 is fully characterized at 3 V and 5 V and is optimized for low-voltage applications.

The TLV2221, exhibiting high input impedance and low noise, is excellent for small-signal conditioning for high-impedance sources, such as piezoelectric transducers. Because of the micropower dissipation levels combined with 3-V operation, these devices work well in hand-held monitoring and remote-sensing applications. In addition, the rail-to-rail output feature with single or split supplies makes this family a great choice when interfacing with analog-to-digital converters (ADCs).

With a total area of 5.6mm², the SOT-23 package only requires one third the board space of the standard 8-pin SOIC package. This ultra-small package allows designers to place single amplifiers very close to the signal source, minimizing noise pick-up from long PCB traces. TI has also taken special care to provide a pinout that is optimized for board layout (see Figure 1). Both inputs are separated by GND to prevent coupling or leakage paths. The OUT and IN– terminals are on the same end of the board to provide negative feedback. Finally, gain setting resistors and decoupling capacitor are easily placed around the package.

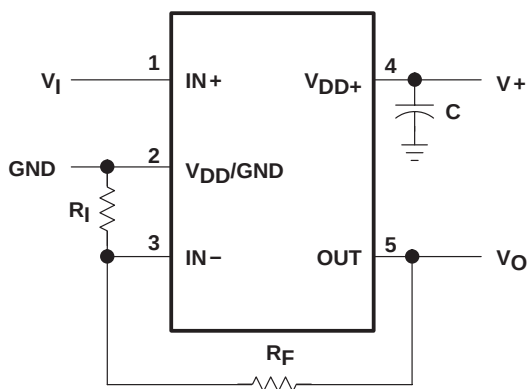


Figure 1. Typical Surface Mount Layout for a Fixed-Gain Noninverting Amplifier



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AVAILABLE OPTIONS

T_A	V_{IOmax} AT 25°C	PACKAGED DEVICES	SYMBOL	CHIP FORM [‡] (Y)
		SOT-23 (DBV) [†]		
0°C to 70°C	3 mV	TLV2221CDBV	VADC	TLV2221Y
–40°C to 85°C	3 mV	TLV2221IDBV	VADI	

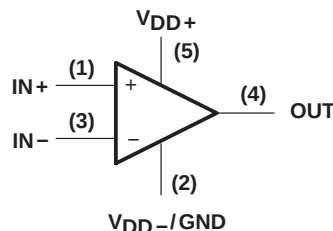
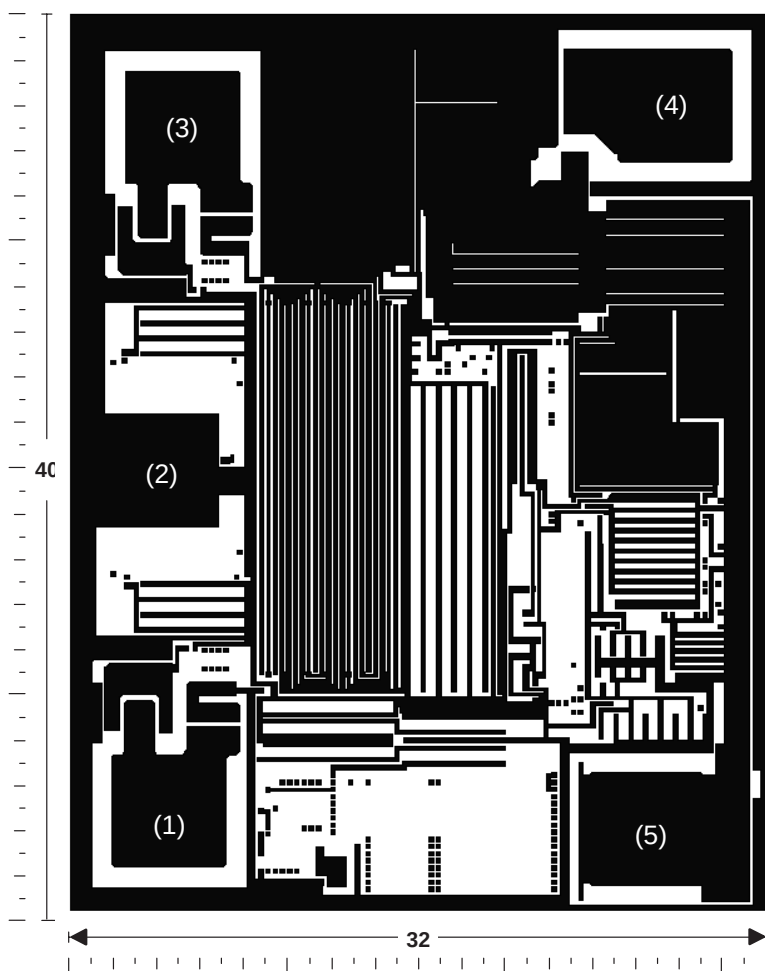
[†] The DBV package available in tape and reel only.

[‡] Chip forms are tested at $T_A = 25^\circ\text{C}$ only.

TLV2221Y chip information

This chip, when properly assembled, displays characteristics similar to the TLV2221C. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. This chip may be mounted with conductive epoxy or a gold-silicon preform.

BONDING PAD ASSIGNMENTS



CHIP THICKNESS: 10 MILS TYPICAL

BONDING PADS: 4×4 MILS MINIMUM

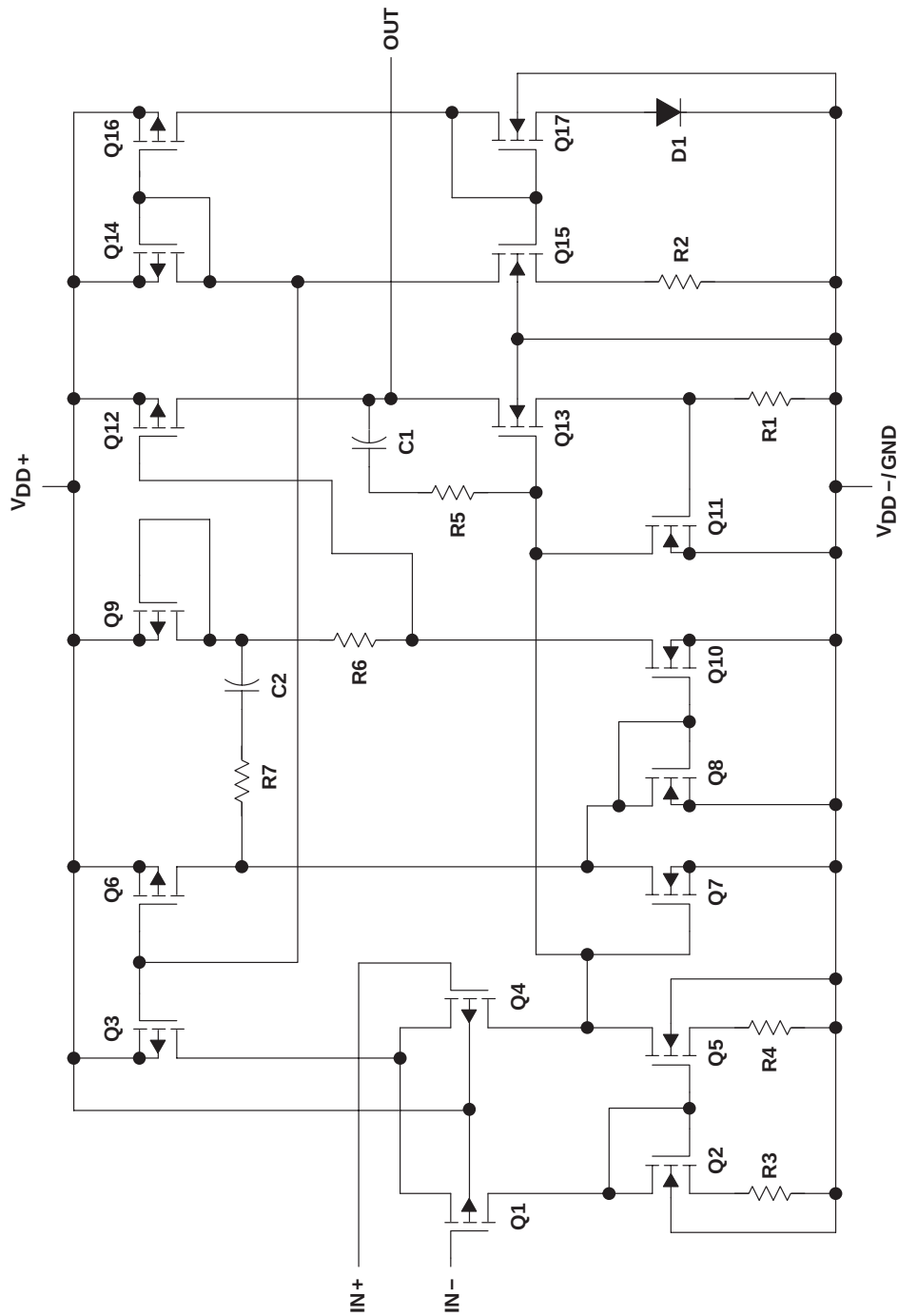
$T_{jmax} = 150^\circ\text{C}$

TOLERANCES ARE $\pm 10\%$.

ALL DIMENSIONS ARE IN MILS.

PIN (2) IS INTERNALLY CONNECTED TO BACKSIDE OF CHIP.

equivalent schematic



COMPONENT COUNT†	
Transistors	23
Diodes	5
Resistors	11
Capacitors	2

† Includes both amplifiers and all ESD, bias, and trim circuitry

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{DD} (see Note 1)	12 V
Differential input voltage, V_{ID} (see Note 2)	$\pm V_{DD}$
Input voltage range, V_I (any input, see Note 1)	-0.3 V to V_{DD}
Input current, I_I (each input)	± 5 mA
Output current, I_O	± 50 mA
Total current into V_{DD+}	± 50 mA
Total current out of V_{DD-}	± 50 mA
Duration of short-circuit current (at or below) 25°C (see Note 3)	unlimited
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A : TLV2221C	0°C to 70°C
TLV2221I	-40°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DBV package	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to V_{DD-} .
2. Differential voltages are at the noninverting input with respect to the inverting input. Excessive current flows when input is brought below $V_{DD-} - 0.3$ V.
3. The output can be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING
DBV	150 mW	1.2 mW/°C	96 mW	78 mW

recommended operating conditions

	TLV2221C		TLV2221I		UNIT
	MIN	MAX	MIN	MAX	
Supply voltage, V_{DD} (see Note 1)	2.7	10	2.7	10	V
Input voltage range, V_I	V_{DD-}	$V_{DD+} - 1.3$	V_{DD-}	$V_{DD+} - 1.3$	V
Common-mode input voltage, V_{IC}	V_{DD-}	$V_{DD+} - 1.3$	V_{DD-}	$V_{DD+} - 1.3$	V
Operating free-air temperature, T_A	0	70	-40	85	°C

NOTE 1: All voltage values, except differential voltages, are with respect to V_{DD-} .

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electrical characteristics at specified free-air temperature, $V_{DD} = 3\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A [†]	TLV2221C			TLV2221I			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V _{IO}	Input offset voltage	V _{DD±} = ±1.5 V, V _O = 0, V _{IC} = 0, R _S = 50 Ω		Full range	0.62 3			0.62 3			mV
α _{VIO}	Temperature coefficient of input offset voltage				1			1			μV/°C
	Input offset voltage long-term drift (see Note 4)			25°C	0.003			0.003			μV/mo
I _{IO}	Input offset current			25°C	0.5			0.5			pA
				Full range	150			150			
I _{IB}	Input bias current			25°C	1			1			pA
		Full range	150			150					
V _{ICR}	Common-mode input voltage range	R _S = 50 Ω, V _{IO} ≤5 mV		25°C	0 to 2	−0.3 to 2.2		0 to 2	−0.3 to 2.2	V	
				Full range	0 to 1.7		0 to 1.7				
V _{OH}	High-level output voltage	I _{OH} = −100 μA		25°C	2.97			2.97			V
		I _{OH} = −400 μA		25°C	2.88			2.88			
				Full range	2.5			2.5			
V _{OL}	Low-level output voltage	V _{IC} = 1.5 V, I _{OL} = 50 μA		25°C	15			15			mV
		V _{IC} = 1.5 V, I _{OL} = 500 μA		25°C	150			150			
				Full range	500			500			
A _{VD}	Large-signal differential voltage amplification	V _{IC} = 1.5 V, V _O = 1 V to 2 V	R _L = 2 kΩ [‡]	25°C	2	3		2	3	V/mV	
				Full range	1			1			
			R _L = 1 MΩ [‡]	25°C	250			250			
r _{id}	Differential input resistance			25°C	10 ¹²			10 ¹²			Ω
r _{ic}	Common-mode input resistance			25°C	10 ¹²			10 ¹²			Ω
c _{ic}	Common-mode input capacitance	f = 10 kHz		25°C	6			6			pF
z _O	Closed-loop output impedance	f = 10 kHz, A _V = 10		25°C	90			90			Ω
CMRR	Common-mode rejection ratio	V _{IC} = 0 to 1.7 V, V _O = 1.5 V, R _S = 50 Ω		25°C	70	82		70	82	dB	
				Full range	65			65			
k _{SVR}	Supply voltage rejection ratio (ΔV _{DD} /ΔV _{IO})	V _{DD} = 2.7 V to 8 V, V _{IC} = V _{DD} /2, No load		25°C	80	95		80	95	dB	
				Full range	80			80			
I _{DD}	Supply current	V _O = 1.5 V, No load		25°C	100	150		100	150	μA	
				Full range	200			200			

† Full range for the TLV2221C is 0°C to 70°C. Full range for the TLV2221I is -40°C to 85°C.

‡ Referenced to 1.5 V

NOTE 4: Typical values are based on the input offset voltage shift observed through 500 hours of operating life test at $T_A = 150^\circ\text{C}$ extrapolated to $T_A = 25^\circ\text{C}$ using the Arrhenius equation and assuming an activation energy of 0.96 eV.

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operating characteristics at specified free-air temperature, $V_{DD} = 3\text{ V}$

PARAMETER		TEST CONDITIONS		T _A [†]	TLV2221C			TLV2221I			UNIT	
					MIN	TYP	MAX	MIN	TYP	MAX		
SR	Slew rate at unity gain	V _O = 1.1 V to 1.9 V, R _L = 2 kΩ [‡] , C _L = 100 pF [‡]		25°C	0.1	0.18		0.1	0.18		V/μs	
				Full range	0.05			0.05				
V _n	Equivalent input noise voltage	f = 10 Hz		25°C	120			120			nV/√Hz	
		f = 1 kHz		25°C	20			20				
V _{N(PP)}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 1 Hz		25°C	680			680			nV	
		f = 0.1 Hz to 10 Hz		25°C	860			860				
I _n	Equivalent input noise current			25°C	0.6			0.6			fA/√Hz	
THD+N	Total harmonic distortion plus noise	V _O = 1 V to 2 V, f = 20 kHz, R _L = 2 kΩ [‡]	A _V = 1	25°C	2.52%			2.52%				
			A _V = 10		7.01%			7.01%				
		V _O = 1 V to 2 V, f = 20 kHz, R _L = 2 kΩ [§]	A _V = 1	25°C	0.076%			0.076%				
			A _V = 10		0.147%			0.147%				
	Gain-bandwidth product	f = 1 kHz, R _L = 2 kΩ [‡] , C _L = 100 pF [‡]		25°C	480			480			kHz	
B _{OM}	Maximum output-swing bandwidth	V _{O(PP)} = 1 V, R _L = 2 kΩ [‡] ,		A _V = 1, C _L = 100 pF [‡]	25°C	30			30			kHz
t _s	Settling time	A _V = −1, Step = 1 V to 2 V, R _L = 2 kΩ [‡] , C _L = 100 pF [‡]	To 0.1%	25°C	4.5			4.5			μs	
			To 0.01%	25°C	6.8			6.8			μs	
φ _m	Phase margin at unity gain	R _L = 2 kΩ [‡] , C _L = 100 pF [‡]		25°C	51°			51°				
	Gain margin			25°C	12			12			dB	

† Full range is –40°C to 85°C.

‡ Referenced to 1.5 V

§ Referenced to 0 V

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electrical characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A [†]	TLV2221C			TLV2221I			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V _{IO}	Input offset voltage	V _{DD±} = ±2.5 V, V _{IC} = 0, V _O = 0, R _S = 50 Ω		Full range	0.61 3			0.61 3			mV
α _{VIO}	Temperature coefficient of input offset voltage				1			1			μV/°C
	Input offset voltage long-term drift (see Note 4)			25°C	0.003			0.003			μV/mo
I _{IO}	Input offset current			25°C	0.5			0.5			pA
				Full range	150			150			
I _{IB}	Input bias current			25°C	1			1			pA
		Full range	150			150					
V _{ICR}	Common-mode input voltage range	R _S = 50 Ω, V _{IO} ≤ 5 mV		25°C	0 to 4	−0.3 to 4.2		0 to 4	−0.3 to 4.2	V	
				Full range	0 to 3.5			0 to 3.5			
V _{OH}	High-level output voltage	I _{OH} = −500 μA I _{OH} = −1 mA		25°C	4.75	4.88		4.75	4.88	V	
					4.5	4.76		4.5	4.76		
V _{OL}	Low-level output voltage	V _{IC} = 2.5 V, I _{OL} = 50 μA		25°C	12			12			mV
		V _{IC} = 2.5 V, I _{OL} = 500 μA		25°C	120			120			
				Full range	500			500			
A _{VD}	Large-signal differential voltage amplification	V _{IC} = 2.5 V, V _O = 1 V to 4 V	R _L = 2 kΩ‡	25°C	3	5		3	5	V/mV	
				Full range	1			1			
			R _L = 1 MΩ‡	25°C	800			800			
r _{id}	Differential input resistance			25°C	10 ¹²			10 ¹²			Ω
r _{ic}	Common-mode input resistance			25°C	10 ¹²			10 ¹²			Ω
c _{ic}	Common-mode input capacitance	f = 10 kHz		25°C	6			6			pF
z _o	Closed-loop output impedance	f = 10 kHz, A _V = 10		25°C	70			70			Ω
CMRR	Common-mode rejection ratio	V _{IC} = 0 to 2.7 V, V _O = 1.5 V, R _S = 50 Ω		25°C	70	85		70	85	dB	
				Full range	65			65			
k _{SVR}	Supply voltage rejection ratio (ΔV _{DD} /ΔV _{IO})	V _{DD} = 4.4 V to 8 V, V _{IC} = V _{DD} /2, No load		25°C	80	95		80	95	dB	
				Full range	80			80			
I _{DD}	Supply current	V _O = 2.5 V, No load		25°C	110 150			110 150			μA
				Full range	200			200			

† Full range for the TLV2221C is 0°C to 70°C. Full range for the TLV2221I is -40°C to 85°C.

‡ Referenced to 2.5 V

NOTE 5: Typical values are based on the input offset voltage shift observed through 500 hours of operating life test at $T_A = 150^\circ\text{C}$ extrapolated to $T_A = 25^\circ\text{C}$ using the Arrhenius equation and assuming an activation energy of 0.96 eV.

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operating characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$

PARAMETER		TEST CONDITIONS		T _A [†]	TLV2221C			TLV2221I			UNIT	
					MIN	TYP	MAX	MIN	TYP	MAX		
SR	Slew rate at unity gain	V _O = 1.5 V to 3.5 V, R _L = 2 kΩ [‡] , C _L = 100 pF [‡]		25°C	0.1	0.18		0.1	0.18		V/μs	
				Full range	0.05			0.05				
V _n	Equivalent input noise voltage	f = 10 Hz f = 1 kHz		25°C	90			90			nV/√Hz	
				25°C	19			19				
V _{N(PP)}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 1 Hz f = 0.1 Hz to 10 Hz		25°C	800			800			nV	
				25°C	960			960				
I _n	Equivalent input noise current			25°C	0.6			0.6			fA/√Hz	
THD+N	Total harmonic distortion plus noise	V _O = 1.5 V to 3.5 V, f = 20 kHz, R _L = 2 kΩ [‡]	A _V = 1	25°C	2.45%			2.45%				
			A _V = 10		5.54%			5.54%				
		V _O = 1.5 V to 3.5 V, f = 20 kHz, R _L = 2 kΩ [§]	A _V = 1	25°C	0.142%			0.142%				
			A _V = 10		0.257%			0.257%				
	Gain-bandwidth product	f = 1 kHz, R _L = 2 kΩ [‡] , C _L = 100 pF [‡]		25°C	510			510			kHz	
B _{OM}	Maximum output-swing bandwidth	V _{O(PP)} = 1 V, R _L = 2 kΩ [‡]		A _V = 1, C _L = 100 pF [‡]	25°C	40			40			kHz
t _s	Settling time	A _V = -1, Step = 1.5 V to 3.5 V, R _L = 2 kΩ [‡] , C _L = 100 pF [‡]	To 0.1%	25°C	6.8			6.8			μs	
			To 0.01%	25°C	9.2			9.2				
φ _m	Phase margin at unity gain	R _L = 2 kΩ [‡] , C _L = 100 pF [‡]		25°C	52°			52°				
	Gain margin			25°C	12			12			dB	

† Full range is –40°C to 85°C.

‡ Referenced to 2.5 V

§ Referenced to 0 V

electrical characteristics at $V_{DD} = 3\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLV2221Y			UNIT
		MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_{DD} = \pm 1.5\text{ V}$, $V_{IC} = 0$, $V_O = 0$, $R_S = 50\ \Omega$		620		μV
I_{IO} Input offset current			0.5		pA
I_{IB} Input bias current			1		pA
V_{ICR} Common-mode input voltage range	$ V_{IO} \leq 5\text{ mV}$, $R_S = 50\ \Omega$		-0.3 to 2.2		V
V_{OH} High-level output voltage	$I_{OH} = -100\ \mu\text{A}$		2.97		V
V_{OL} Low-level output voltage	$V_{IC} = 1.5\text{ V}$, $I_{OL} = 50\ \mu\text{A}$		15		mV
	$V_{IC} = 1.5\text{ V}$, $I_{OL} = 500\ \mu\text{A}$		150		
A_{VD} Large-signal differential voltage amplification	$V_O = 1\text{ V to } 2\text{ V}$	$R_L = 2\text{ k}\Omega^\dagger$	3		V/mV
		$R_L = 1\text{ M}\Omega^\dagger$	250		
r_{id} Differential input resistance			10^{12}		Ω
r_{ic} Common-mode input resistance			10^{12}		Ω
c_{ic} Common-mode input capacitance	$f = 10\text{ kHz}$		6		pF
z_o Closed-loop output impedance	$f = 10\text{ kHz}$, $A_V = 10$		90		Ω
CMRR Common-mode rejection ratio	$V_{IC} = 0\text{ to } 1.7\text{ V}$, $V_O = 0$, $R_S = 50\ \Omega$		82		dB
k_{SVR} Supply voltage rejection ratio ($\Delta V_{DD}/\Delta V_{IO}$)	$V_{DD} = 2.7\text{ V to } 8\text{ V}$, $V_{IC} = 0$, No load		95		dB
I_{DD} Supply current	$V_O = 0$, No load		100		μA

† Referenced to 1.5 V

electrical characteristics at $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLV2221Y			UNIT
		MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_{DD} = \pm 1.5\text{ V}$, $V_{IC} = 0$, $V_O = 0$, $R_S = 50\ \Omega$		610		μV
I_{IO} Input offset current			0.5		pA
I_{IB} Input bias current			1		pA
V_{ICR} Common-mode input voltage range	$ V_{IO} \leq 5\text{ mV}$, $R_S = 50\ \Omega$		-0.3 to 4.2		V
V_{OH} High-level output voltage	$I_{OH} = -500\ \mu\text{A}$		4.88		V
V_{OL} Low-level output voltage	$V_{IC} = 2.5\text{ V}$, $I_{OL} = 50\ \mu\text{A}$		12		mV
	$V_{IC} = 2.5\text{ V}$, $I_{OL} = 500\ \mu\text{A}$		120		
A_{VD} Large-signal differential voltage amplification	$V_O = 1\text{ V to } 4\text{ V}$	$R_L = 2\text{ k}\Omega^\dagger$	5		V/mV
		$R_L = 1\text{ M}\Omega^\dagger$	800		
r_{id} Differential input resistance			10^{12}		Ω
r_{ic} Common-mode input resistance			10^{12}		Ω
c_{ic} Common-mode input capacitance	$f = 10\text{ kHz}$		6		pF
z_o Closed-loop output impedance	$f = 10\text{ kHz}$, $A_V = 10$		70		Ω
CMRR Common-mode rejection ratio	$V_{IC} = 0\text{ to } 1.7\text{ V}$, $V_O = 0$, $R_S = 50\ \Omega$		85		dB
k_{SVR} Supply voltage rejection ratio ($\Delta V_{DD}/\Delta V_{IO}$)	$V_{DD} = 2.7\text{ V to } 8\text{ V}$, $V_{IC} = 0$, No load		95		dB
I_{DD} Supply current	$V_O = 0$, No load		110		μA

† Referenced to 2.5 V

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TYPICAL CHARACTERISTICS

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SR	Slew rate	vs Load capacitance vs Free-air temperature	34 35
V_O	Inverting large-signal pulse response	vs Time	36, 37
V_O	Voltage-follower large-signal pulse response	vs Time	38, 39
V_O	Inverting small-signal pulse response	vs Time	40, 41
V_O	Voltage-follower small-signal pulse response	vs Time	42, 43
V_n	Equivalent input noise voltage	vs Frequency	44, 45
	Input noise voltage (referred to input)	Over a 10-second period	46
THD + N	Total harmonic distortion plus noise	vs Frequency	47
	Gain-bandwidth product	vs Free-air temperature vs Supply voltage	48 49
ϕ_m	Phase margin	vs Frequency vs Load capacitance	22, 23 52, 53
	Gain margin	vs Load capacitance	50, 51
B_1	Unity-gain bandwidth	vs Load capacitance	54, 55

TYPICAL CHARACTERISTICS

**DISTRIBUTION OF TLV2211
INPUT OFFSET VOLTAGE**

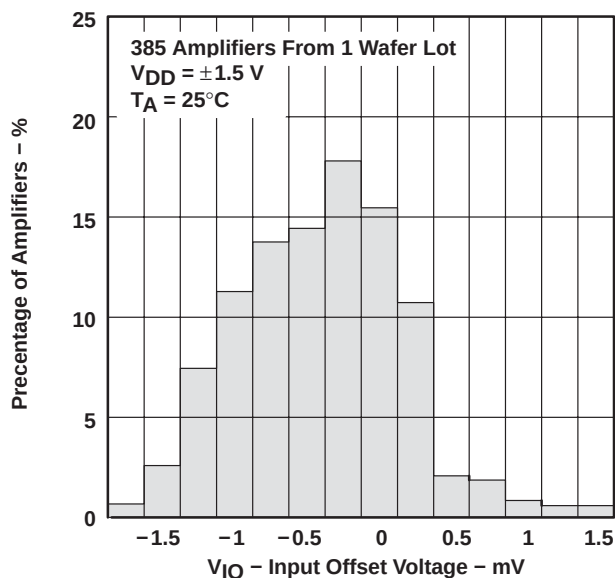


Figure 2

**DISTRIBUTION OF TLV2211
INPUT OFFSET VOLTAGE**

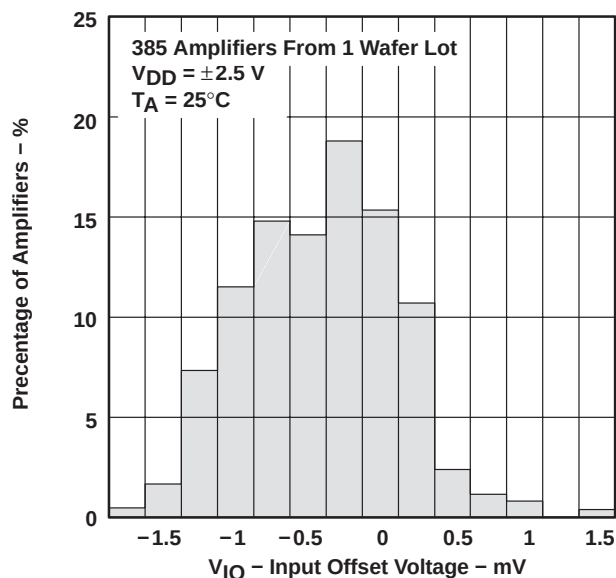


Figure 3

**INPUT OFFSET VOLTAGE[†]
vs
COMMON-MODE INPUT VOLTAGE**

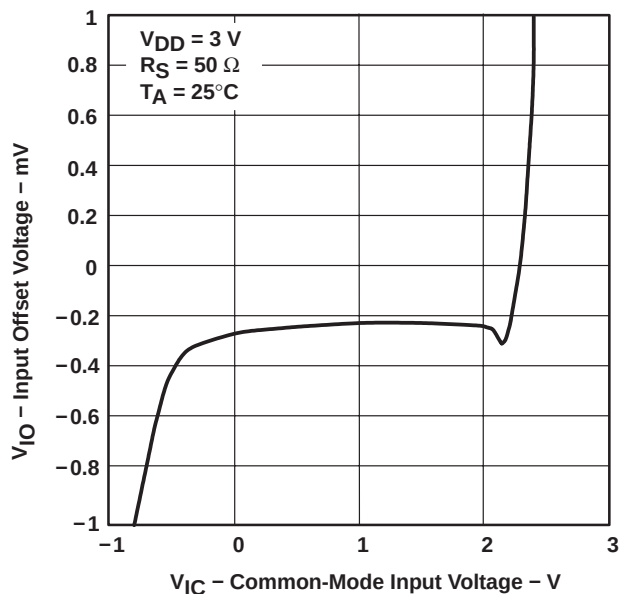


Figure 4

**INPUT OFFSET VOLTAGE[†]
vs
COMMON-MODE INPUT VOLTAGE**

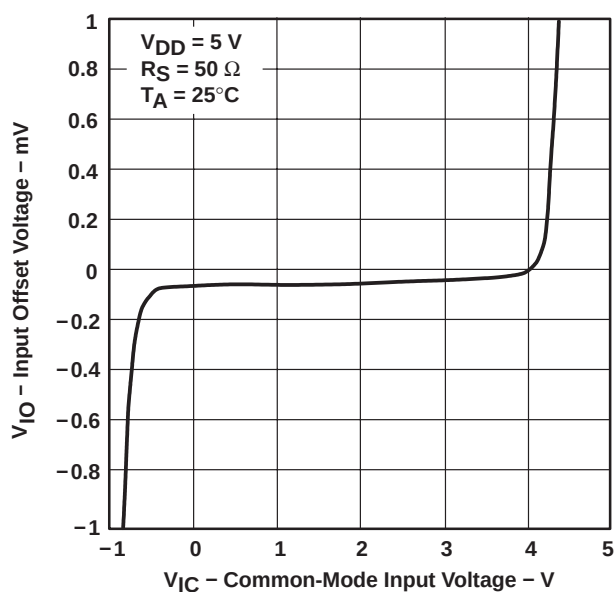


Figure 5

[†] For all curves where $V_{DD} = 5 \text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3 \text{ V}$, all loads are referenced to 1.5 V.

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TYPICAL CHARACTERISTICS

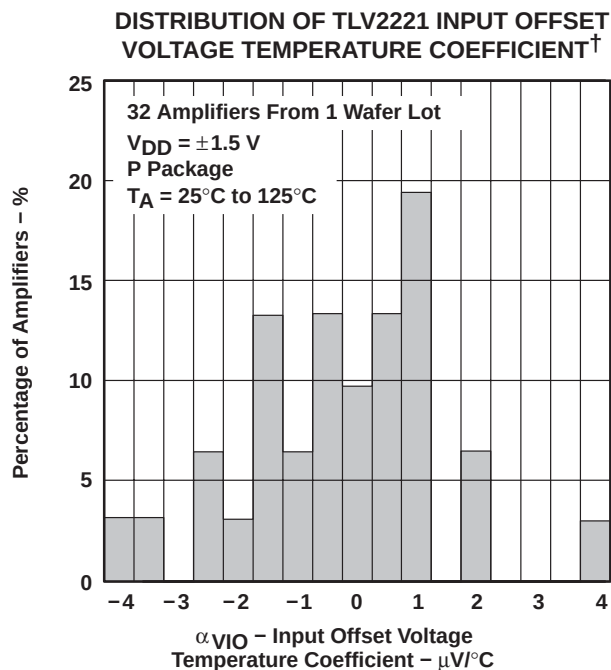


Figure 6

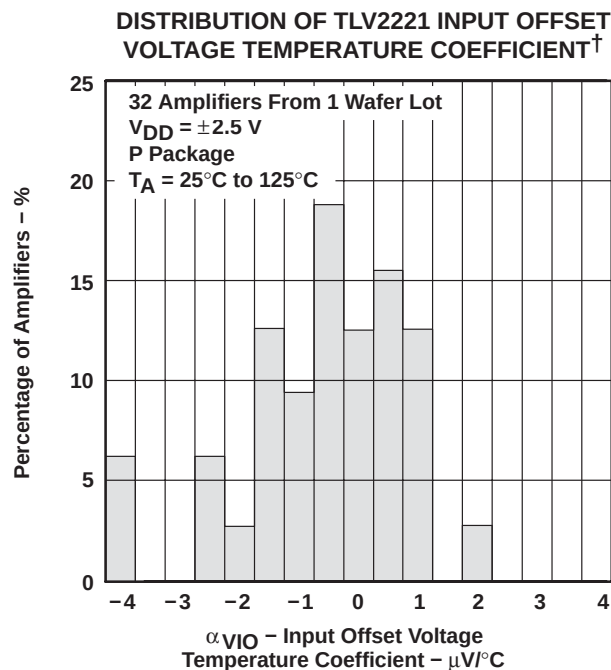


Figure 7

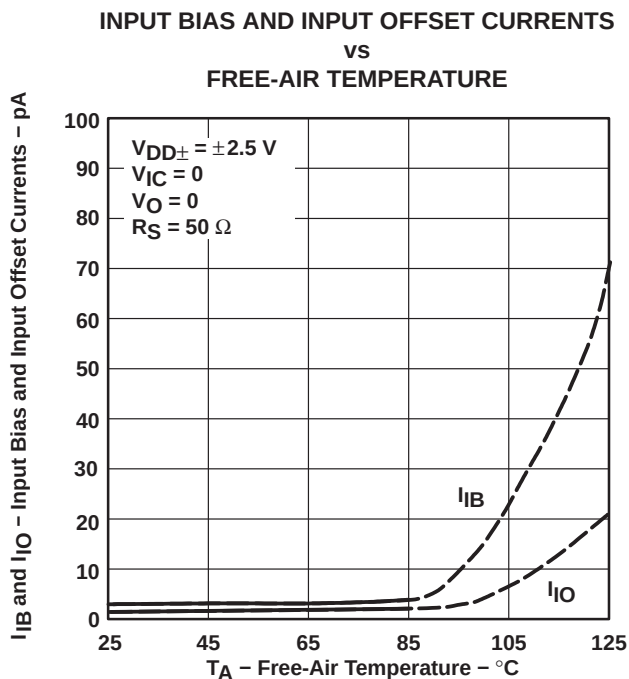


Figure 8

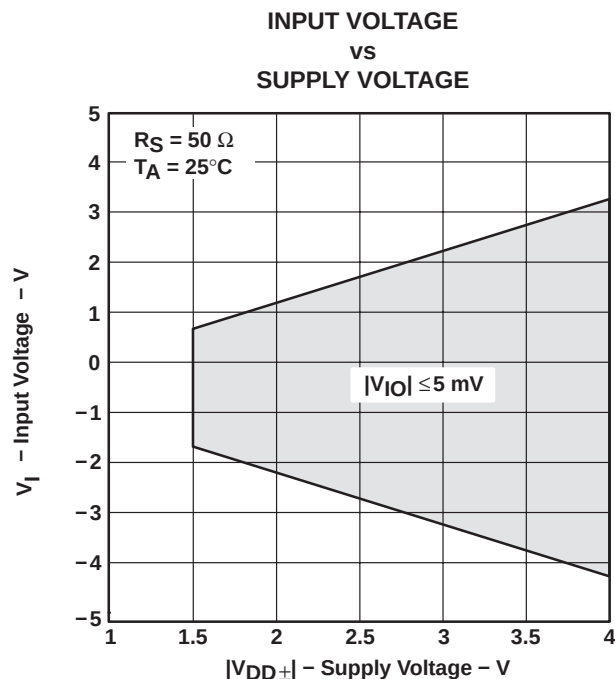
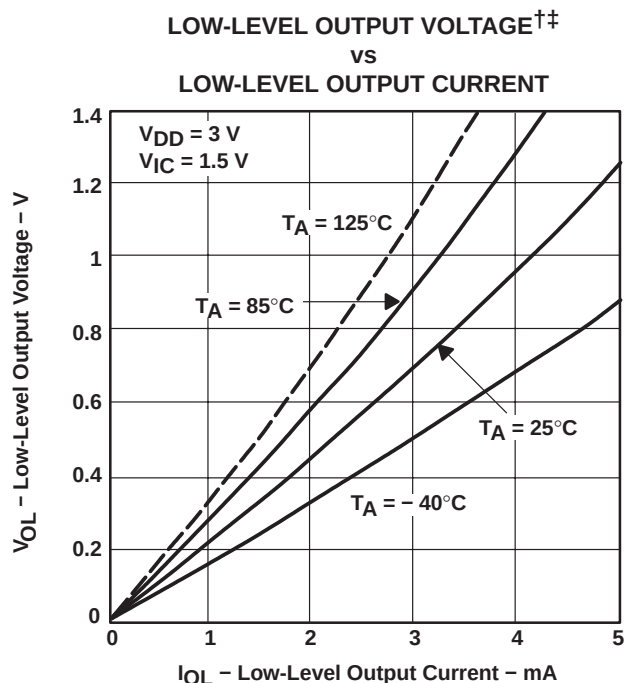
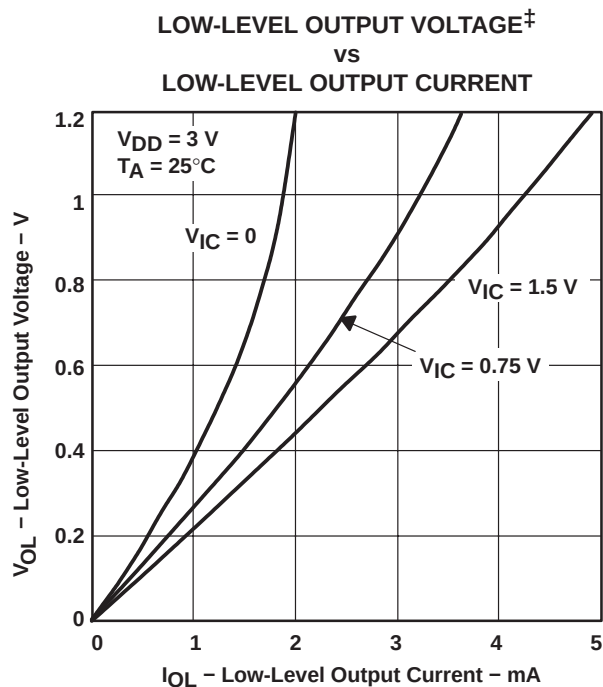
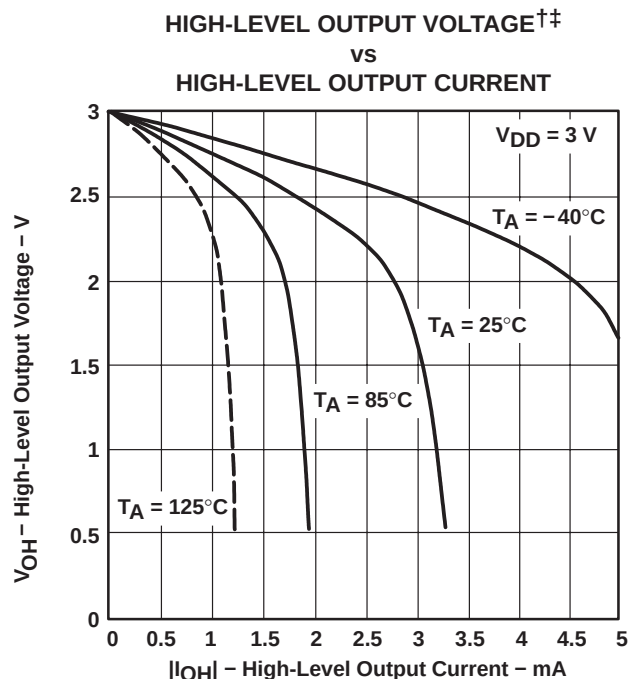
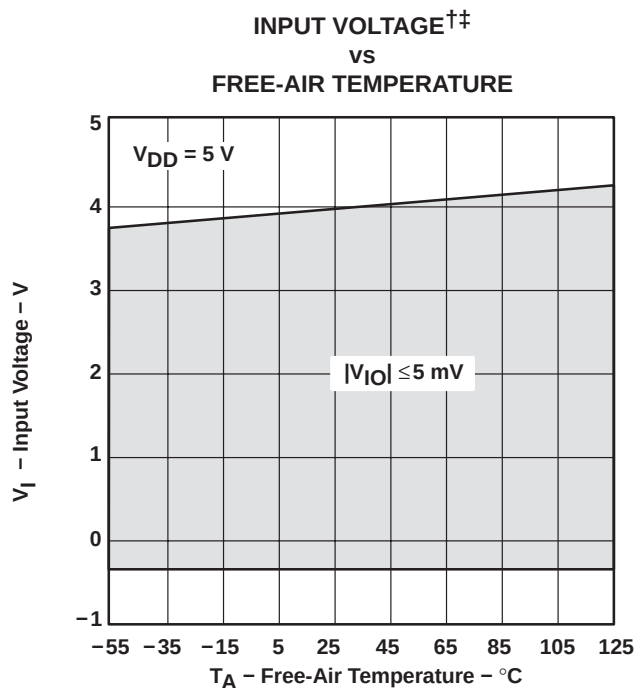


Figure 9

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS



[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

[‡] For all curves where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3\text{ V}$, all loads are referenced to 1.5 V.

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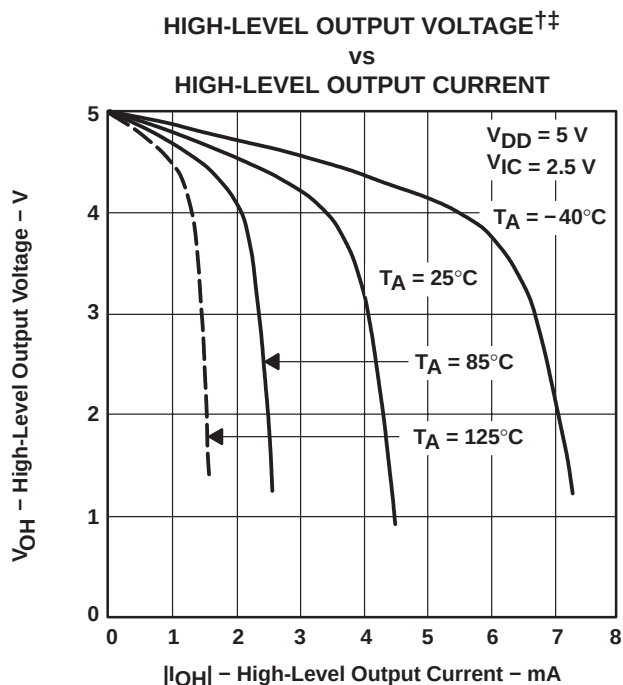


Figure 14

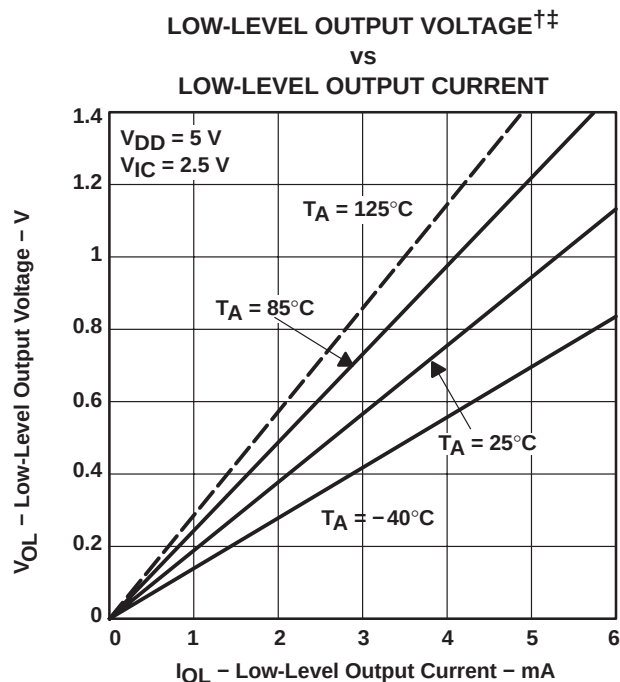


Figure 15

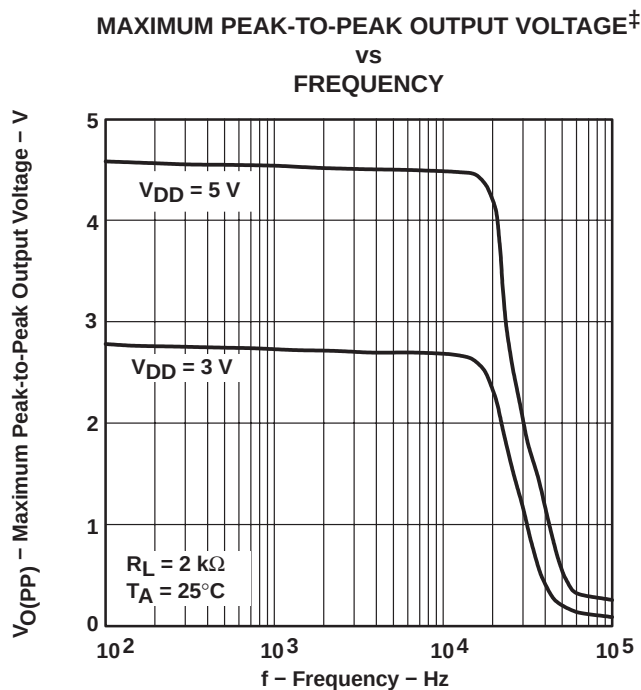


Figure 16

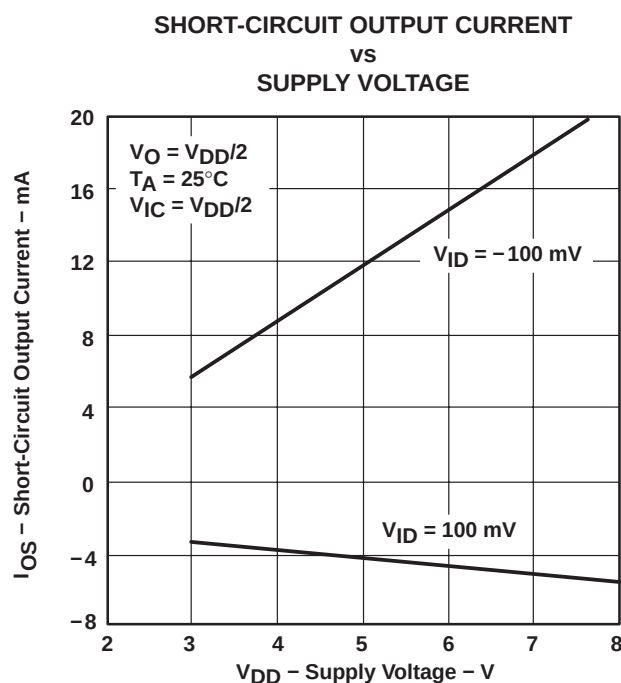
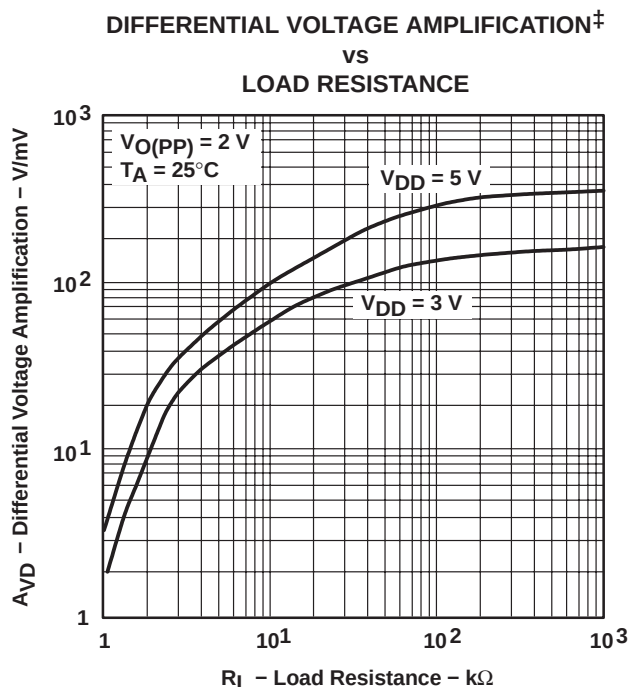
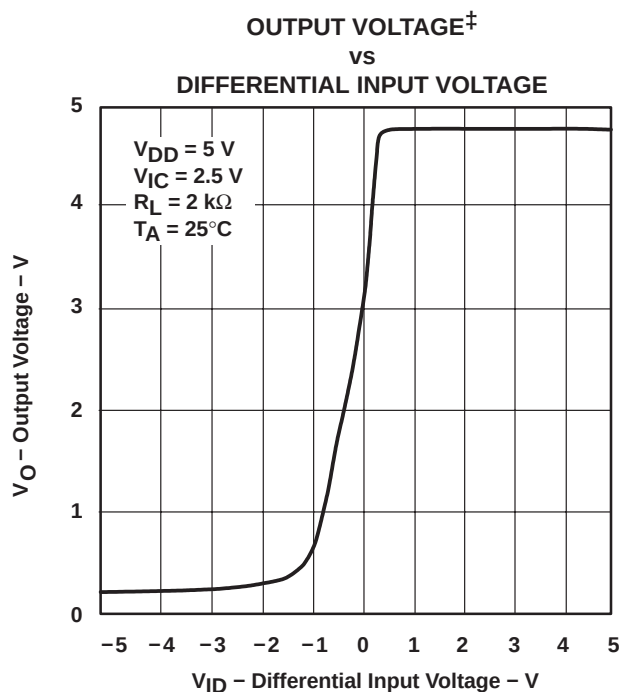
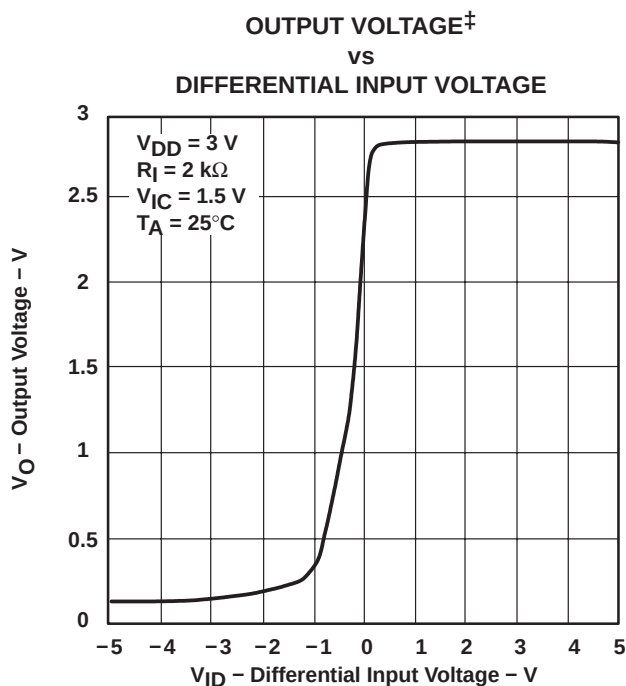
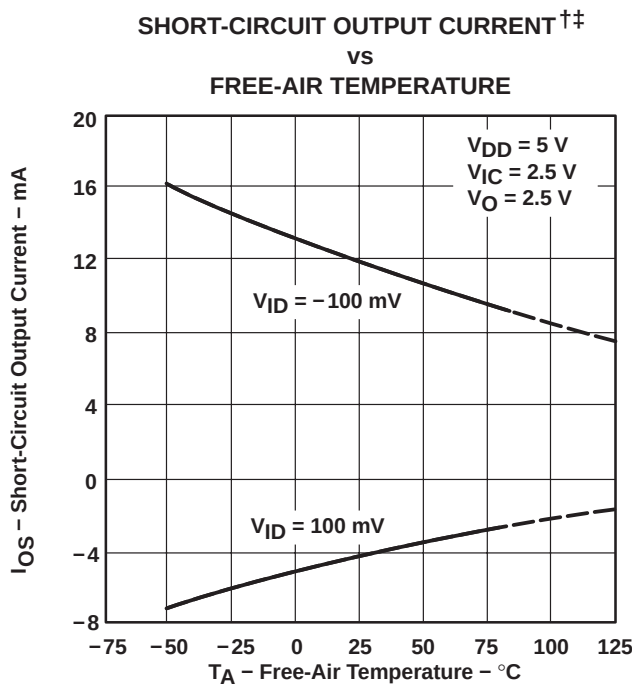


Figure 17

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

[‡] For all curves where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3\text{ V}$, all loads are referenced to 1.5 V.

TYPICAL CHARACTERISTICS



[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

[‡] For all curves where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3\text{ V}$, all loads are referenced to 1.5 V.

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TYPICAL CHARACTERISTICS

**LARGE-SIGNAL DIFFERENTIAL VOLTAGE†
AMPLIFICATION AND PHASE MARGIN
VS
FREQUENCY**

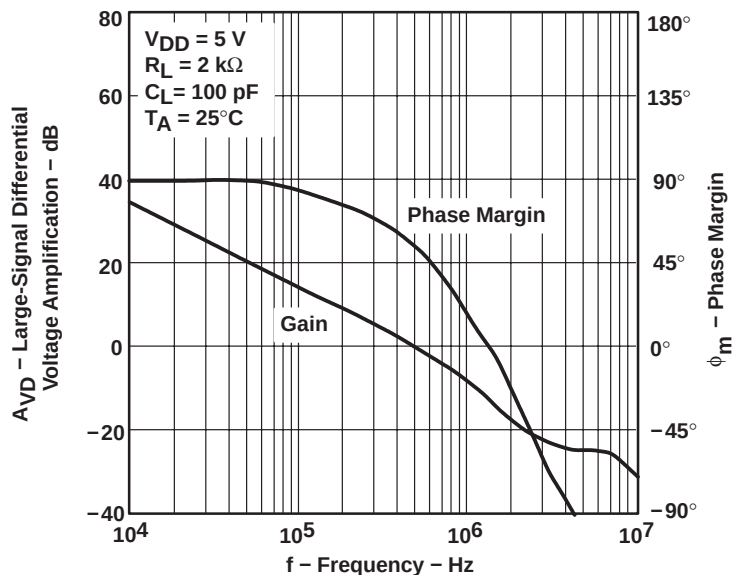


Figure 22

**LARGE-SIGNAL DIFFERENTIAL VOLTAGE
AMPLIFICATION AND PHASE MARGIN†
VS
FREQUENCY**

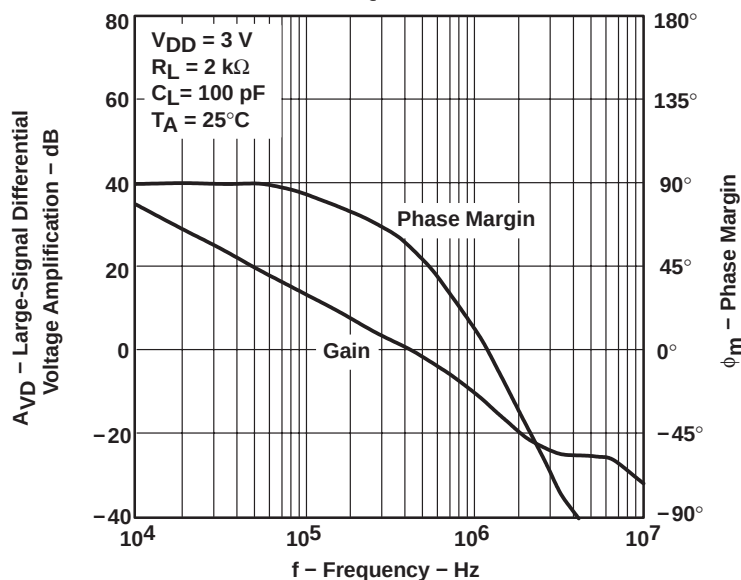


Figure 23

† For all curves where V_{DD} = 5 V, all loads are referenced to 2.5 V. For all curves where V_{DD} = 3 V, all loads are referenced to 1.5 V.

TYPICAL CHARACTERISTICS

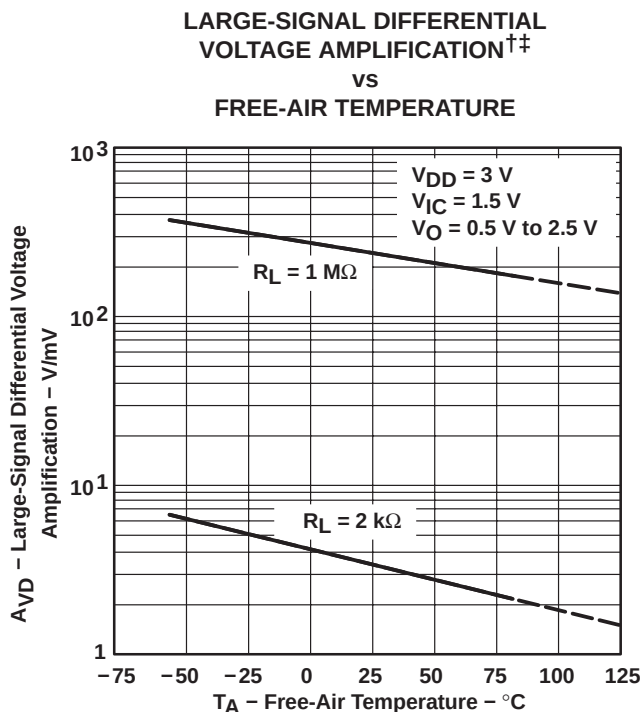


Figure 24

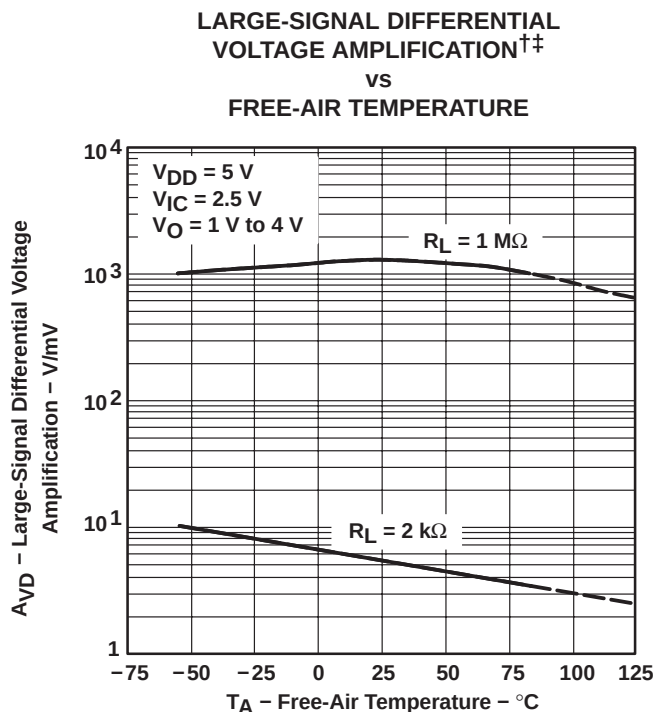


Figure 25

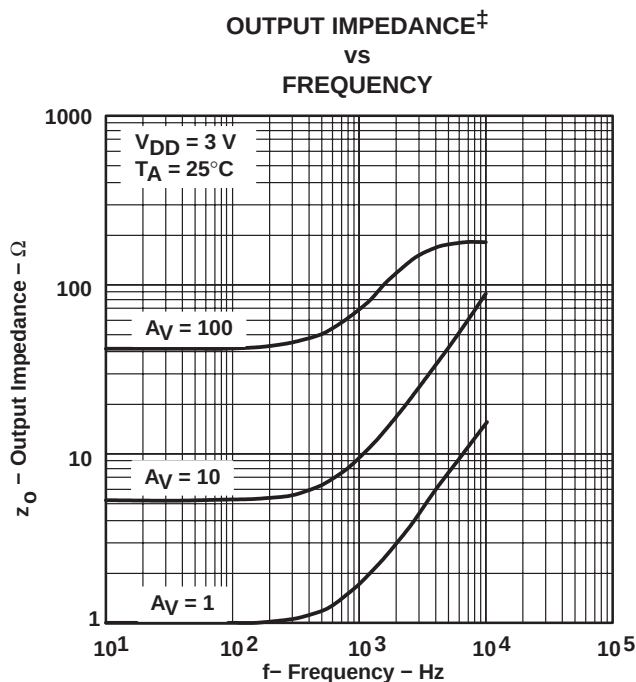


Figure 26

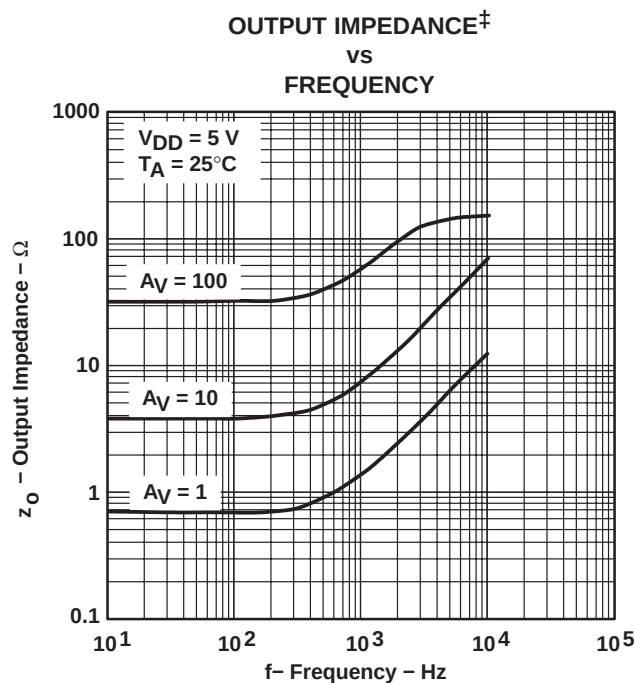


Figure 27

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

[‡] For all curves where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3\text{ V}$, all loads are referenced to 1.5 V.

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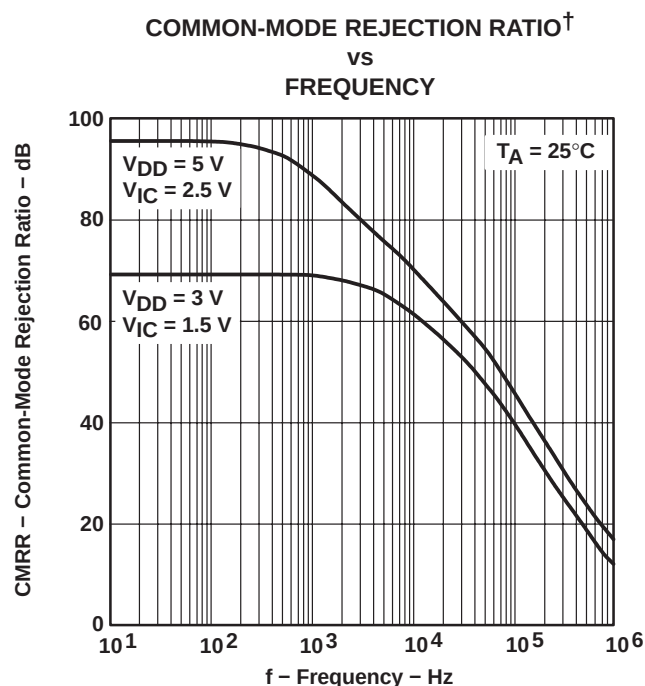


Figure 28

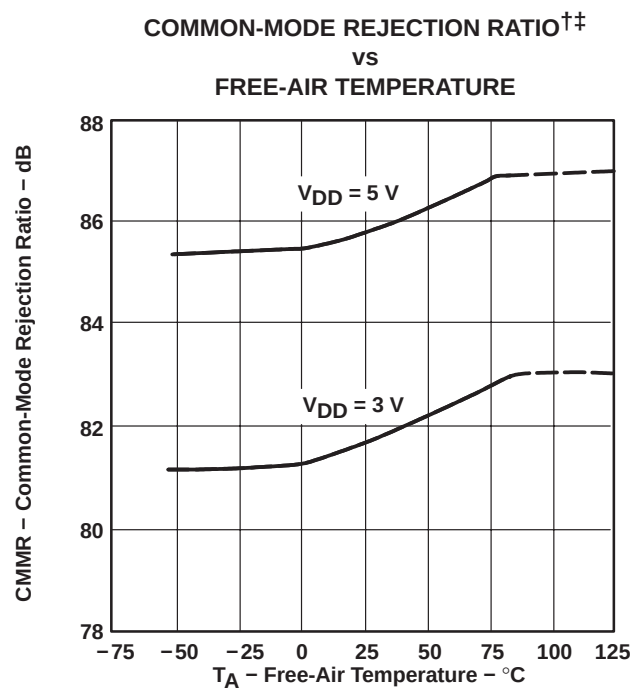


Figure 29

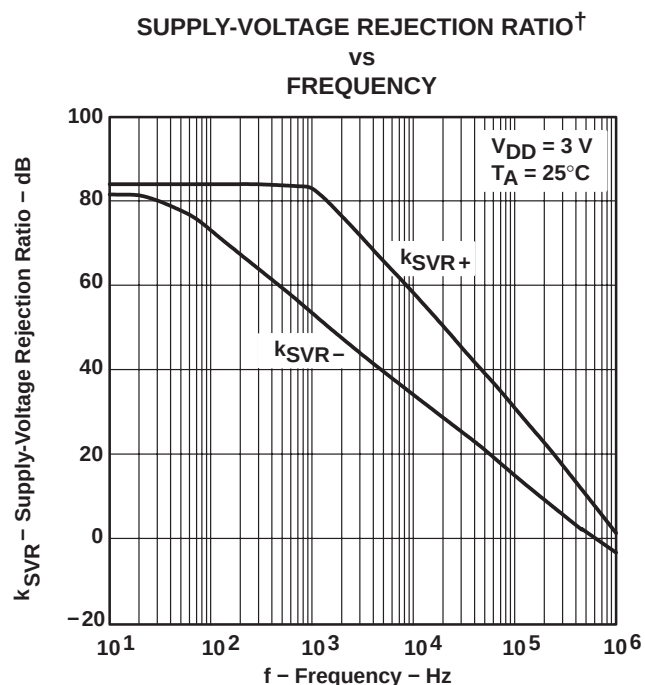


Figure 30

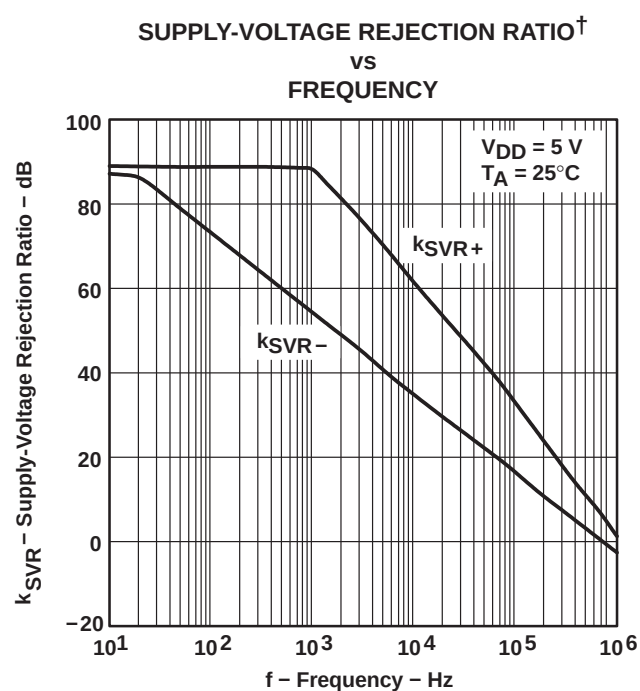


Figure 31

[†] For all curves where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3\text{ V}$, all loads are referenced to 1.5 V.

[‡] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

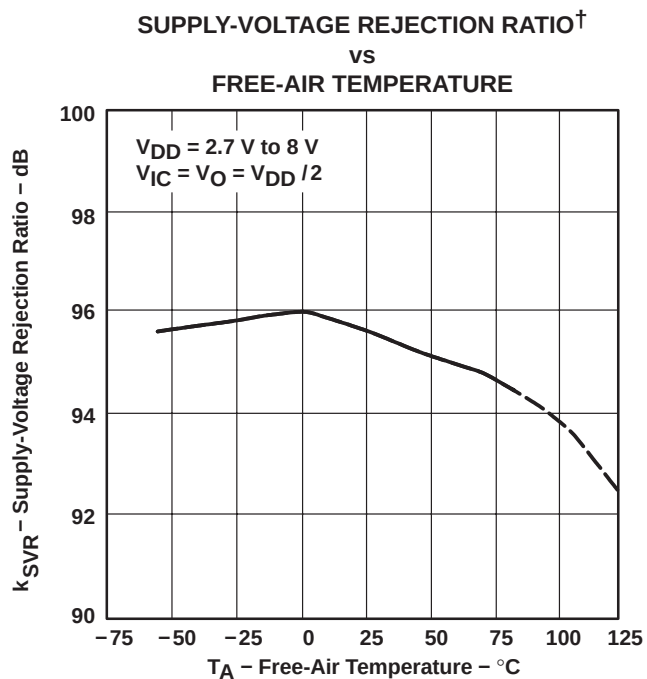


Figure 32

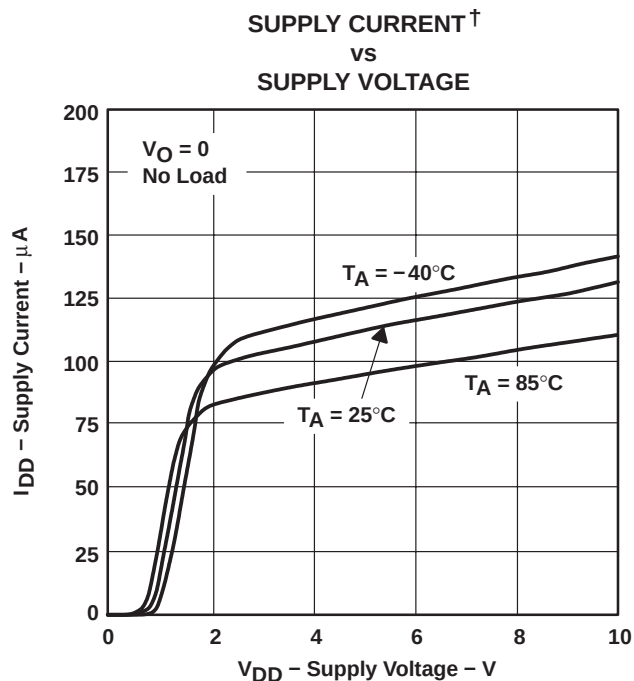


Figure 33

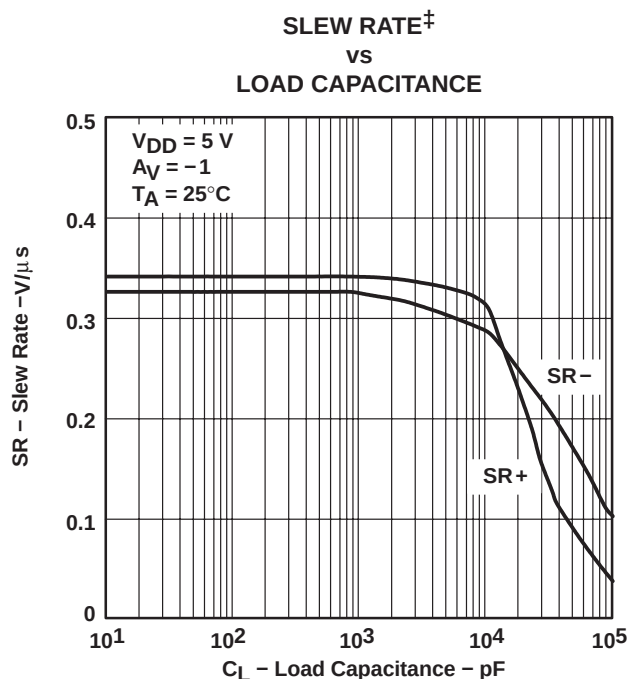


Figure 34

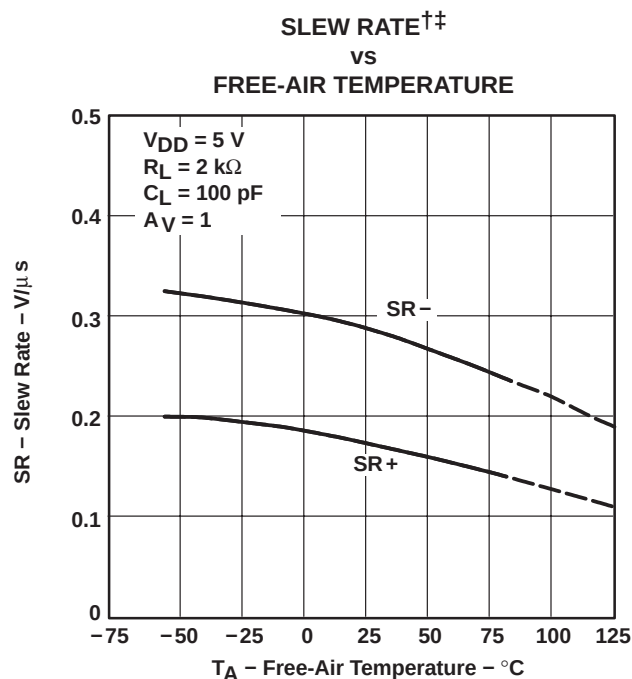


Figure 35

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

‡ For all curves where $V_{DD} = 5 \text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3 \text{ V}$, all loads are referenced to 1.5 V.

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TYPICAL CHARACTERISTICS

INVERTING LARGE-SIGNAL PULSE RESPONSE†

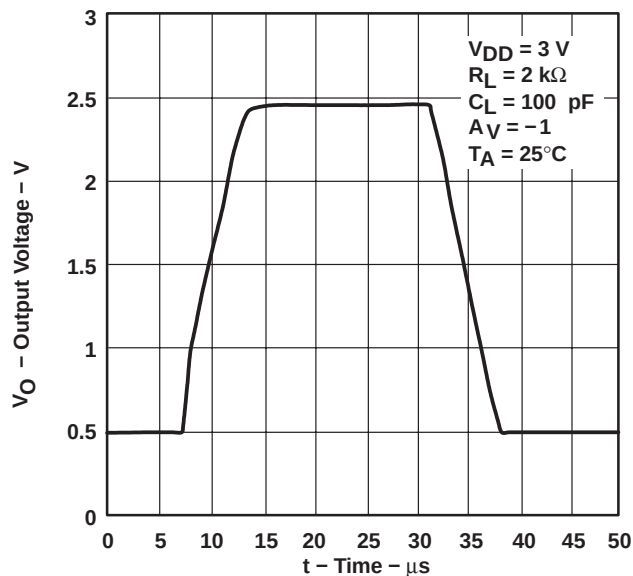


Figure 36

INVERTING LARGE-SIGNAL PULSE RESPONSE†

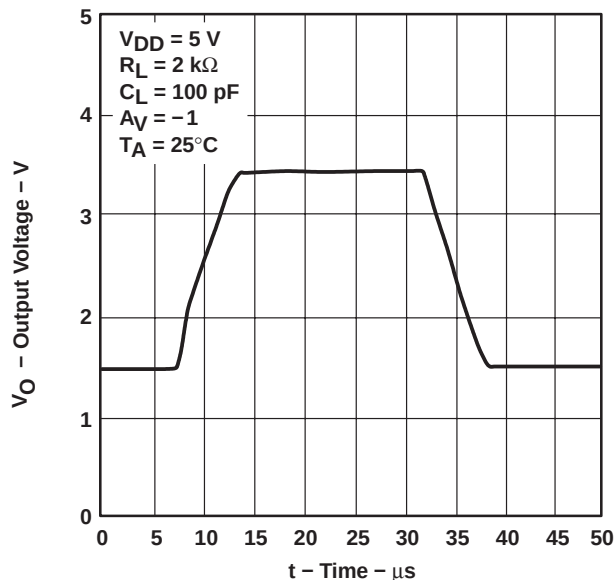


Figure 37

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE†

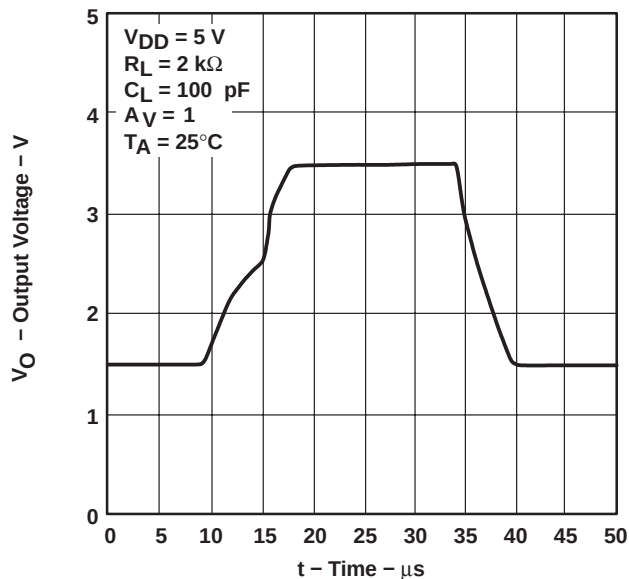


Figure 38

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE†

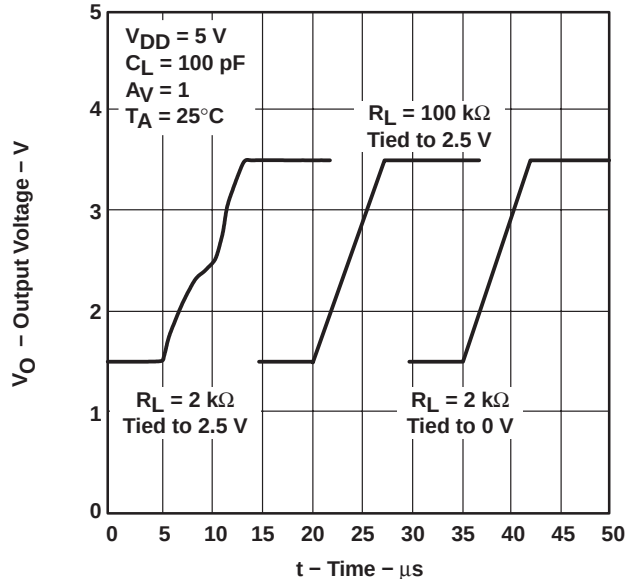


Figure 39

† For all curves where $V_{DD} = 5V$, all loads are referenced to 2.5V. For all curves where $V_{DD} = 3V$, all loads are referenced to 1.5V.

TYPICAL CHARACTERISTICS

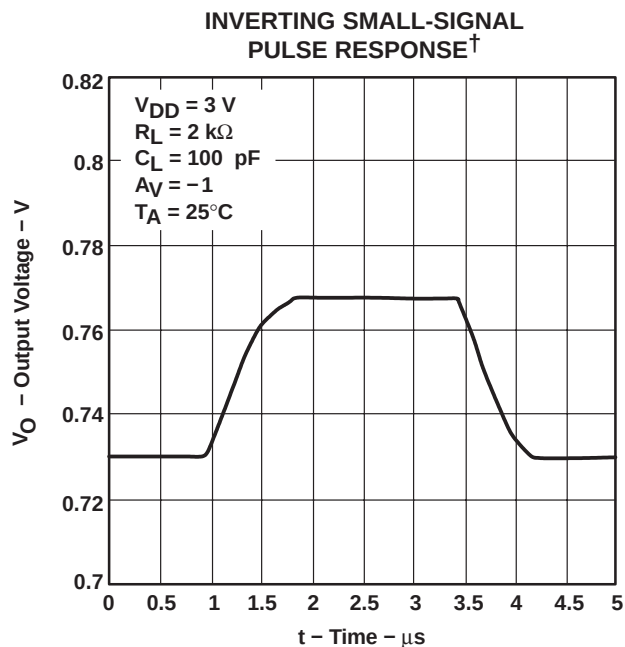


Figure 40

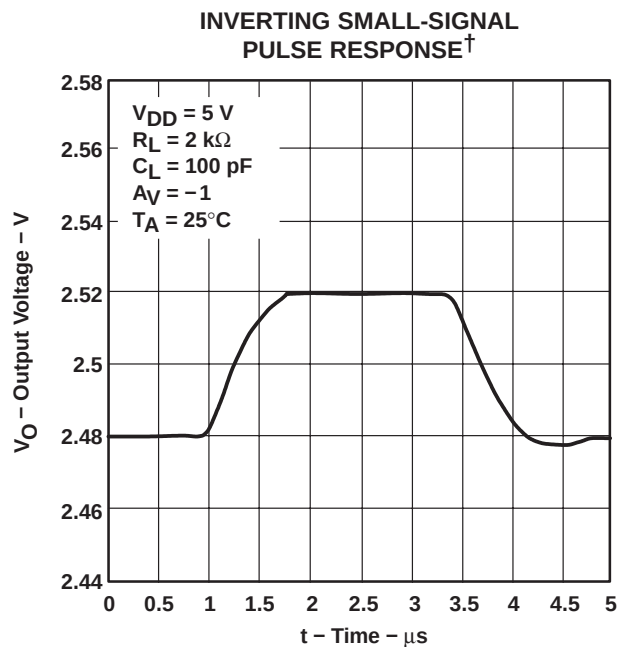


Figure 41

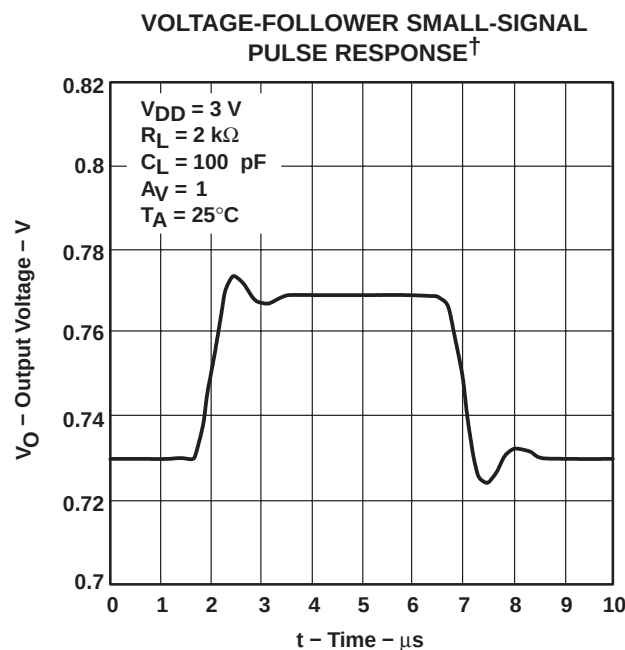


Figure 42

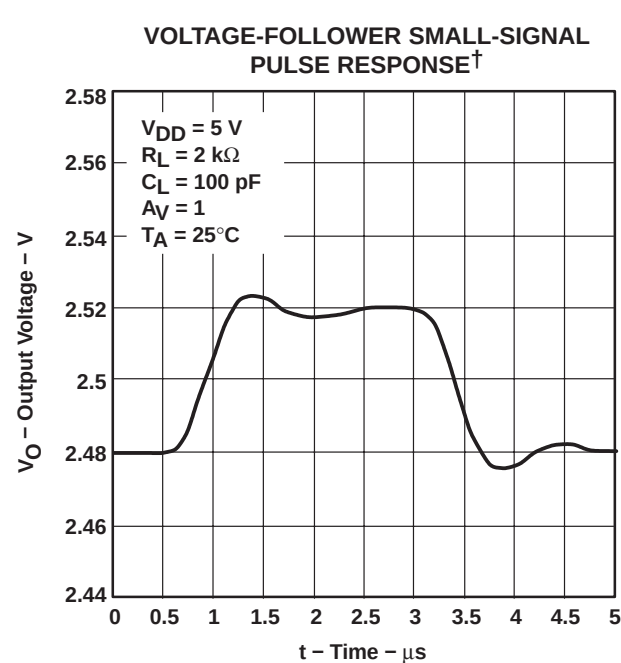


Figure 43

† For all curves where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3\text{ V}$, all loads are referenced to 1.5 V.

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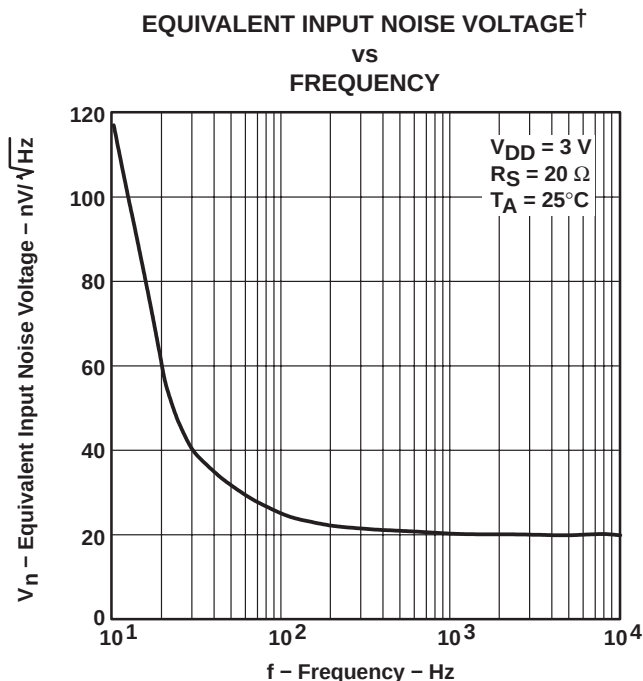


Figure 44

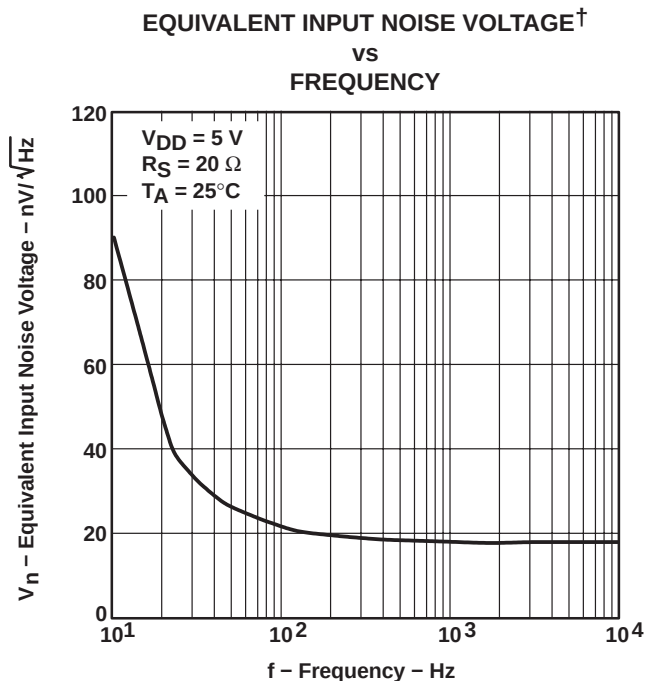


Figure 45

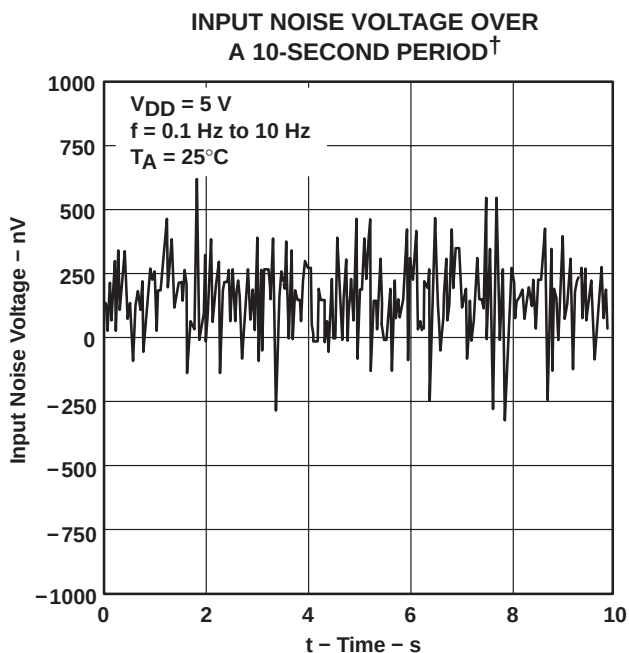


Figure 46

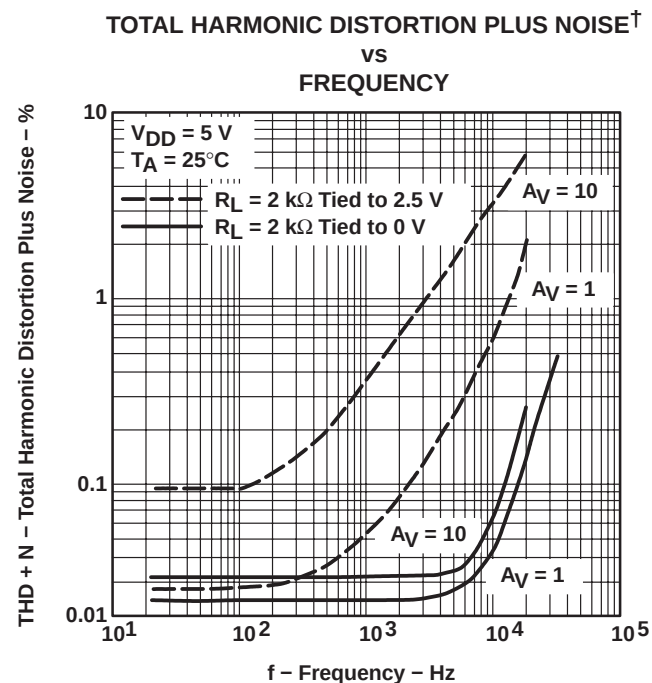


Figure 47

[†] For all curves where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3\text{ V}$, all loads are referenced to 1.5 V.

TYPICAL CHARACTERISTICS

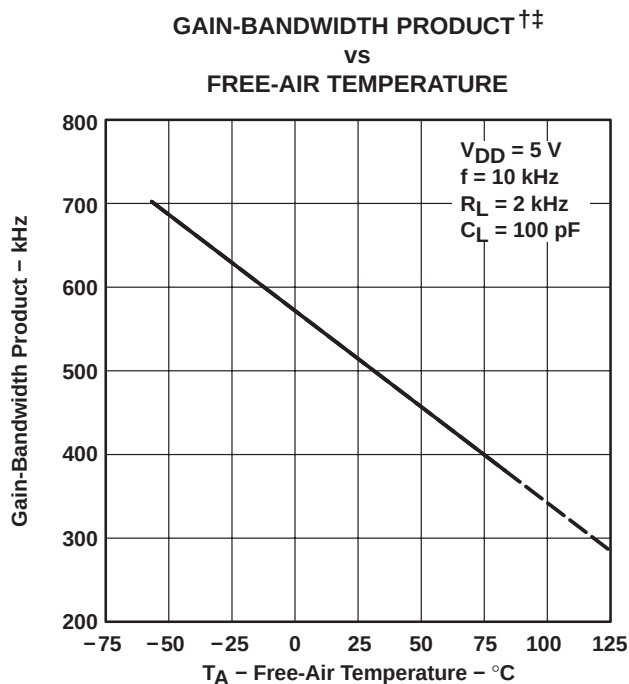


Figure 48

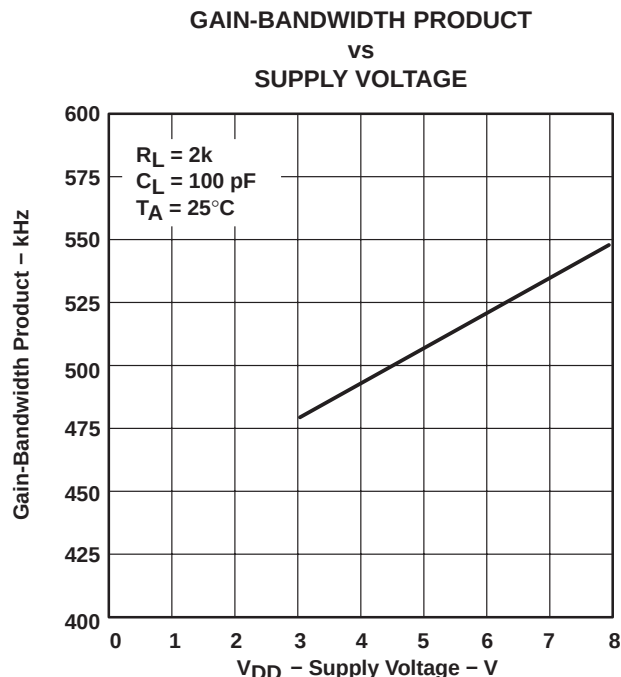


Figure 49

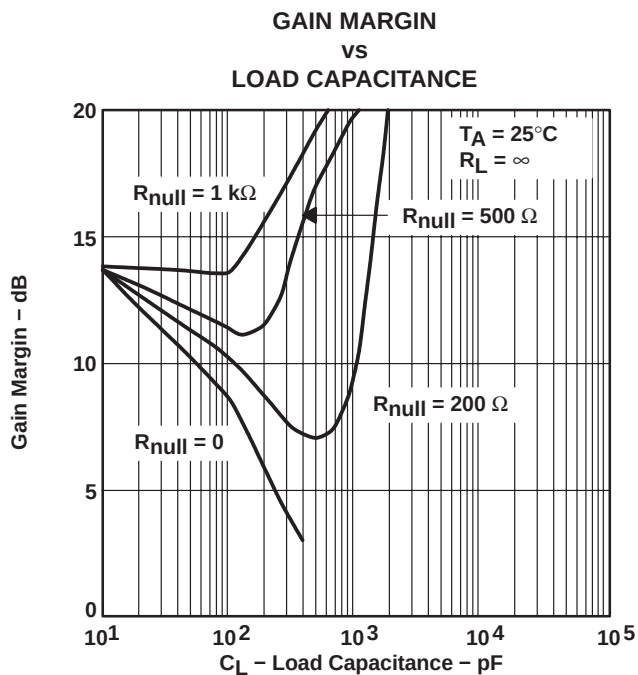


Figure 50

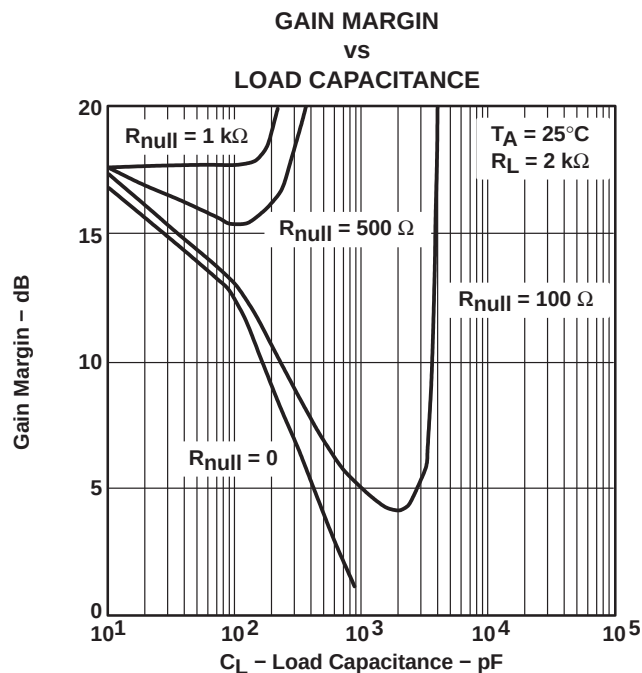


Figure 51

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

[‡] For all curves where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V. For all curves where $V_{DD} = 3\text{ V}$, all loads are referenced to 1.5 V.

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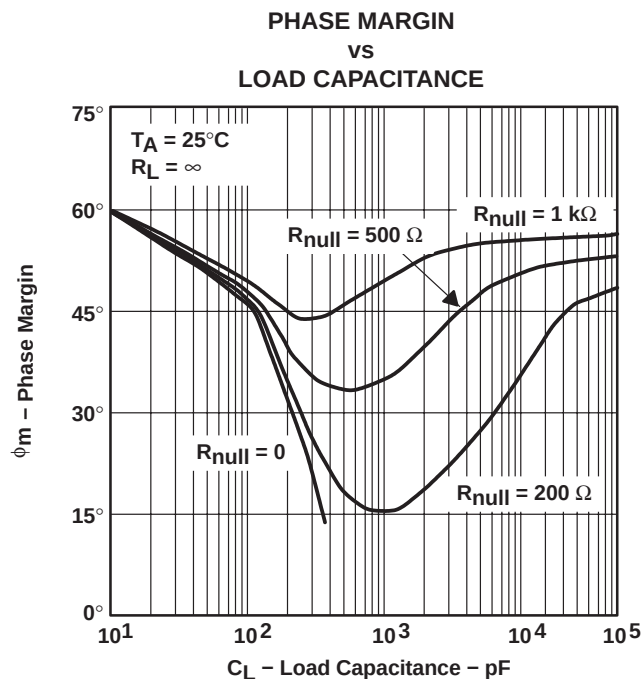


Figure 52

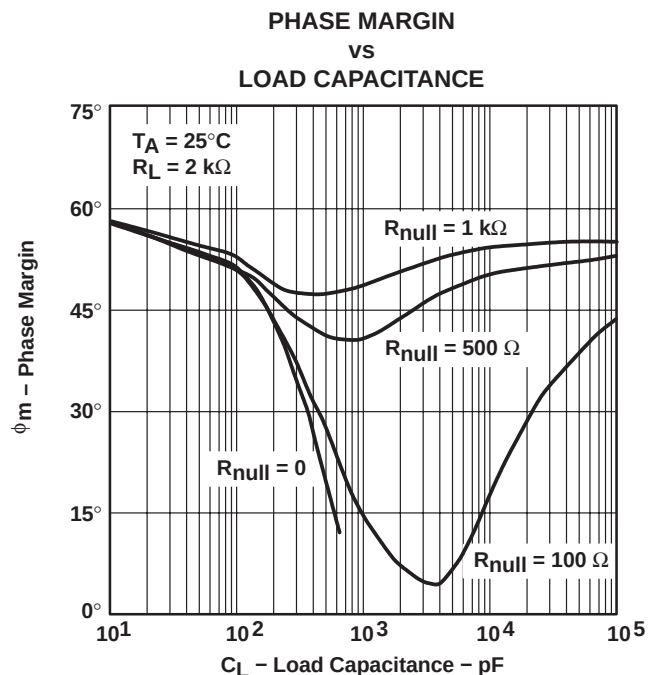


Figure 53

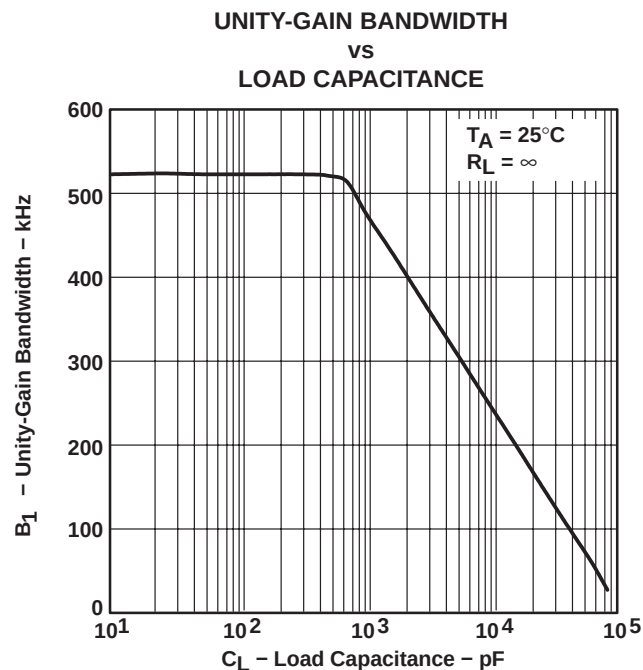


Figure 54

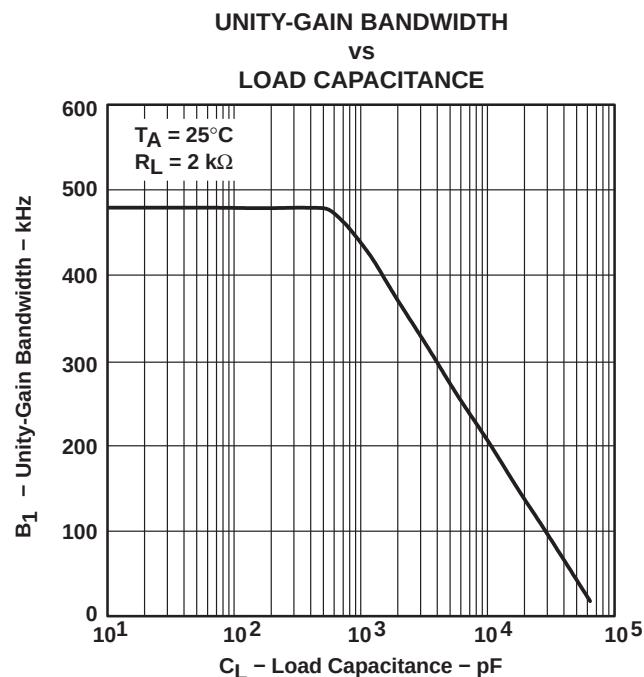


Figure 55

APPLICATION INFORMATION

driving large capacitive loads

The TLV2221 is designed to drive larger capacitive loads than most CMOS operational amplifiers. Figure 50 through Figure 55 illustrate its ability to drive loads greater than 100 pF while maintaining good gain and phase margins ($R_{null} = 0$).

A small series resistor (R_{null}) at the output of the device (Figure 56) improves the gain and phase margins when driving large capacitive loads. Figure 50 through Figure 53 show the effects of adding series resistances of 100 Ω , 200 Ω , 500 Ω , and 1 k Ω . The addition of this series resistor has two effects: the first effect is that it adds a zero to the transfer function and the second effect is that it reduces the frequency of the pole associated with the output load in the transfer function.

The zero introduced to the transfer function is equal to the series resistance times the load capacitance. To calculate the approximate improvement in phase margin, equation 1 can be used.

$$\Delta\phi_{m1} = \tan^{-1} \left(2 \times \pi \times \text{UGBW} \times R_{null} \times C_L \right) \quad (1)$$

where :

$\Delta\phi_{m1}$ = improvement in phase margin

UGBW = unity-gain bandwidth frequency

R_{null} = output series resistance

C_L = load capacitance

The unity-gain bandwidth (UGBW) frequency decreases as the capacitive load increases (Figure 54 and Figure 55). To use equation 1, UGBW must be approximated from Figure 54 and Figure 55.

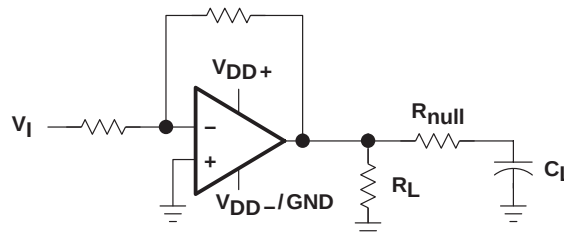


Figure 56. Series-Resistance Circuit

The TLV2221 is designed to provide better sinking and sourcing output currents than earlier CMOS rail-to-rail output devices. This device is specified to sink 500 μA and source 1 mA at $V_{DD} = 5\text{ V}$ at a maximum quiescent I_{DD} of 200 μA . This provides a greater than 80% power efficiency.

When driving heavy dc loads, such as 2 k Ω , the positive edge under slewing conditions can experience some distortion. This condition can be seen in Figure 38. This condition is affected by three factors:

- Where the load is referenced. When the load is referenced to either rail, this condition does not occur. The distortion occurs only when the output signal swings through the point where the load is referenced. Figure 39 illustrates two 2-k Ω load conditions. The first load condition shows the distortion seen for a 2-k Ω load tied to 2.5 V. The third load condition in Figure 39 shows no distortion for a 2-k Ω load tied to 0 V.
- Load resistance. As the load resistance increases, the distortion seen on the output decreases. Figure 39 illustrates the difference seen on the output for a 2-k Ω load and a 100-k Ω load with both tied to 2.5 V.
- Input signal edge rate. Faster input edge rates for a step input result in more distortion than with slower input edge rates.

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APPLICATION INFORMATION

macromodel information

Macromodel information provided was derived using Microsim *Parts*™, the model generation software used with Microsim *PSpice*™. The Boyle macromodel (see Note 6) and subcircuit in Figure 57 are generated using the TLV2221 typical electrical and operating characteristics at $T_A = 25^\circ\text{C}$. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity-gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

NOTE 6: G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, "Macromodeling of Integrated Circuit Operational Amplifiers", *IEEE Journal of Solid-State Circuits*, SC-9, 353 (1974).

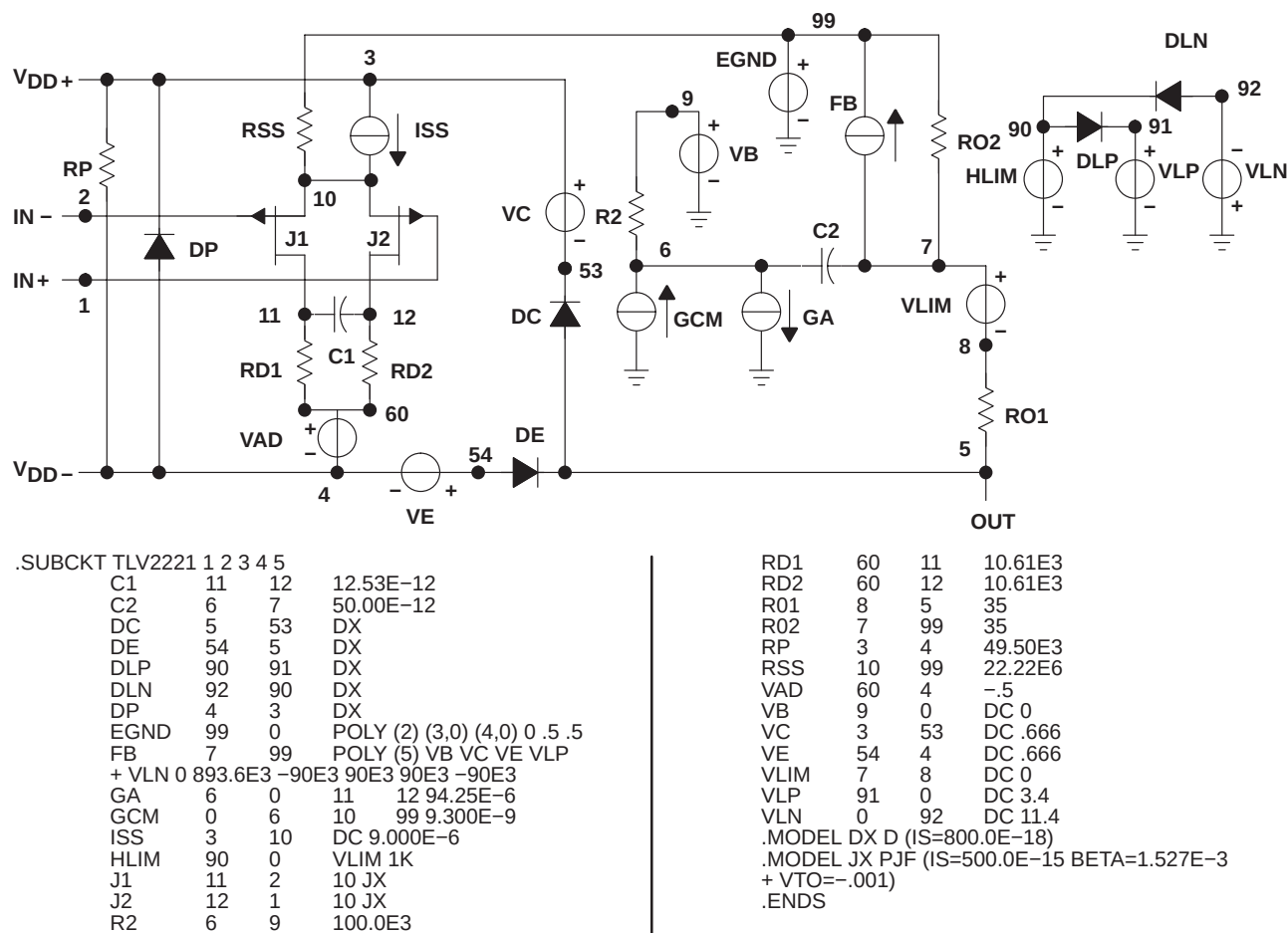


Figure 57. Boyle Macromodel and Subcircuit

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Macromodels, simulation models, or other models provided by TI, directly or indirectly, are not warranted by TI as fully representing all of the specification and operating characteristics of the semiconductor product to which the model relates.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TLV2221CDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	VADC	Samples
TLV2221CDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	VADC	Samples
TLV2221CDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	VADC	Samples
TLV2221CDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	VADC	Samples
TLV2221IDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	VADI	Samples
TLV2221IDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	VADI	Samples
TLV2221IDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		VADI	Samples
TLV2221IDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		VADI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

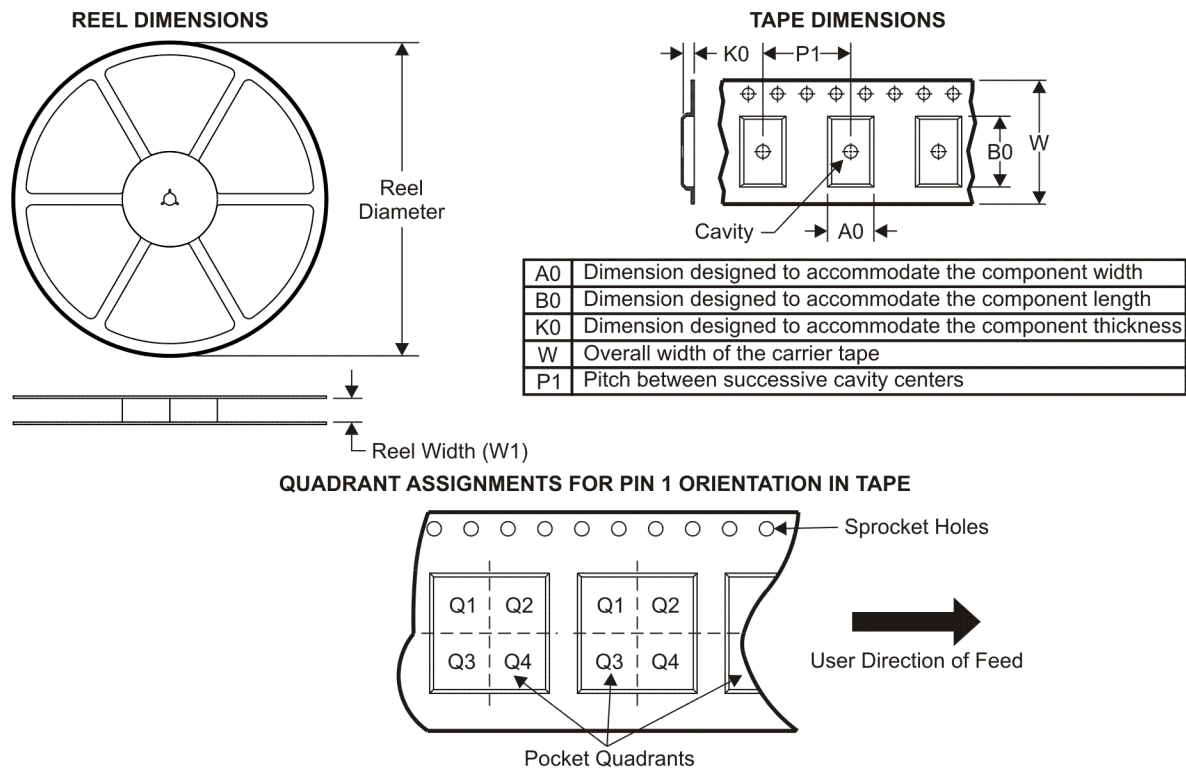
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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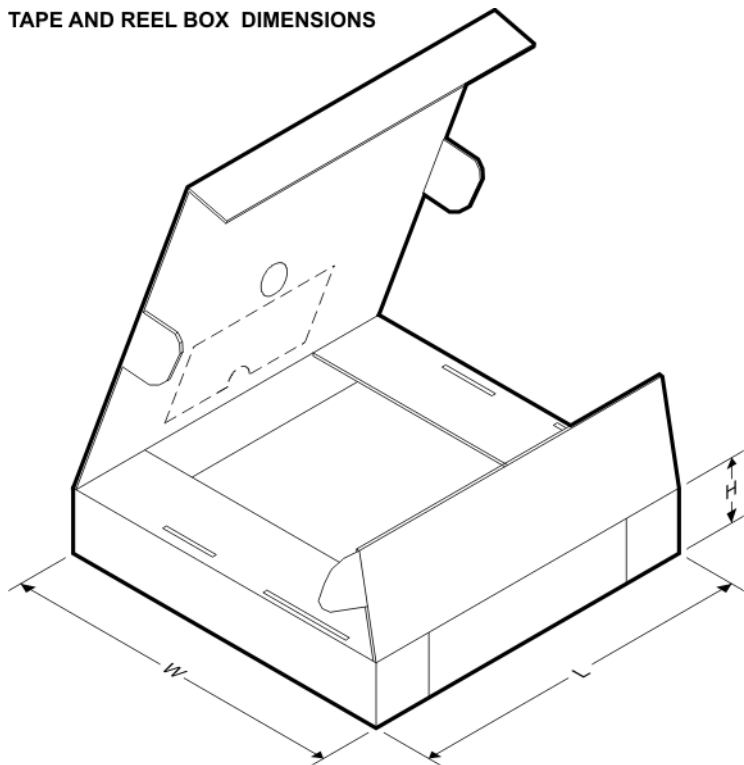
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV2221CDBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TLV2221CDBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TLV2221IDBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TLV2221IDBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

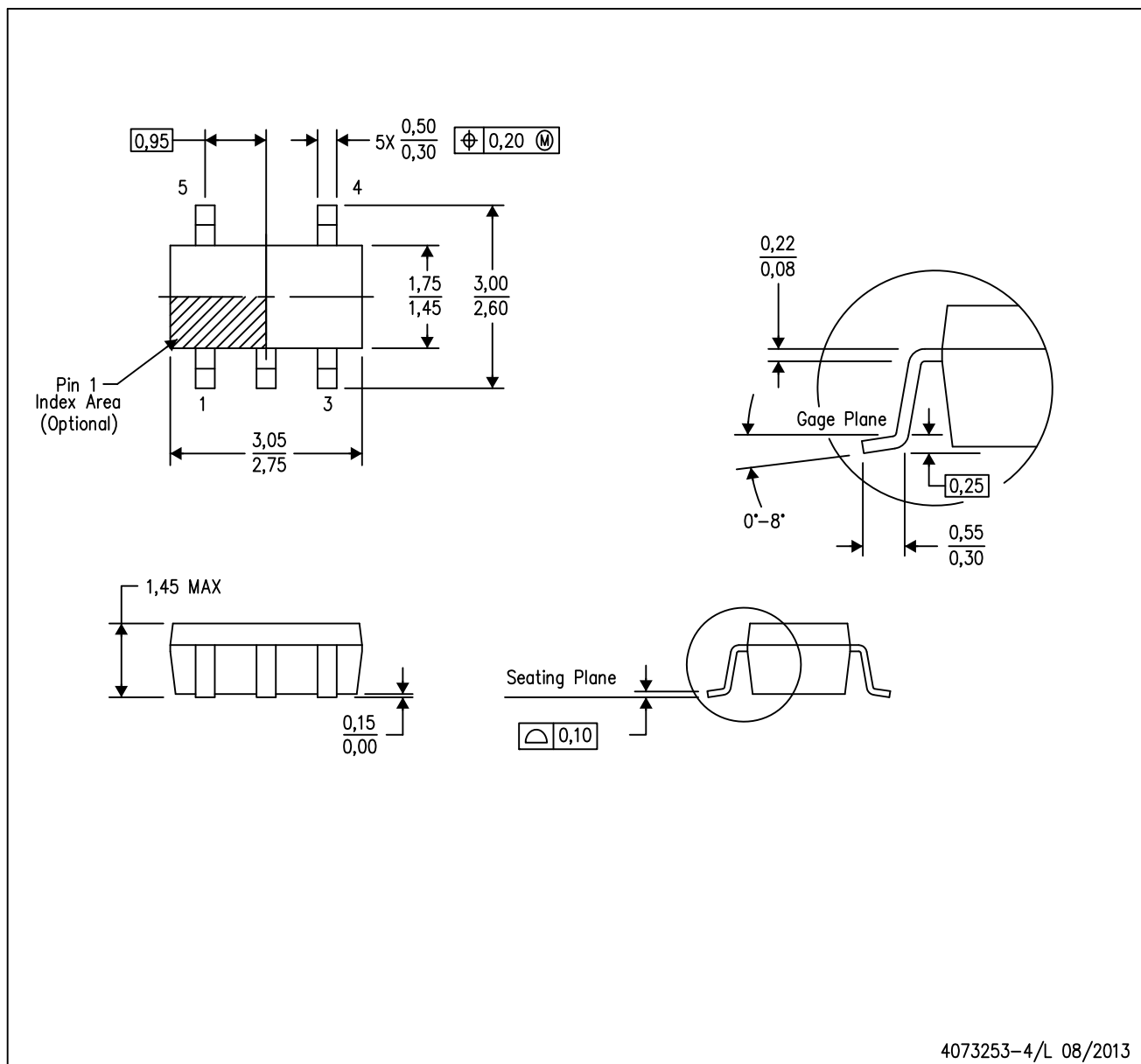


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV2221CDBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TLV2221CDBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TLV2221IDBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TLV2221IDBVT	SOT-23	DBV	5	250	182.0	182.0	20.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

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